



Strangeness in Quark Matter
Bari (Italy), 10 to 15 June 2019

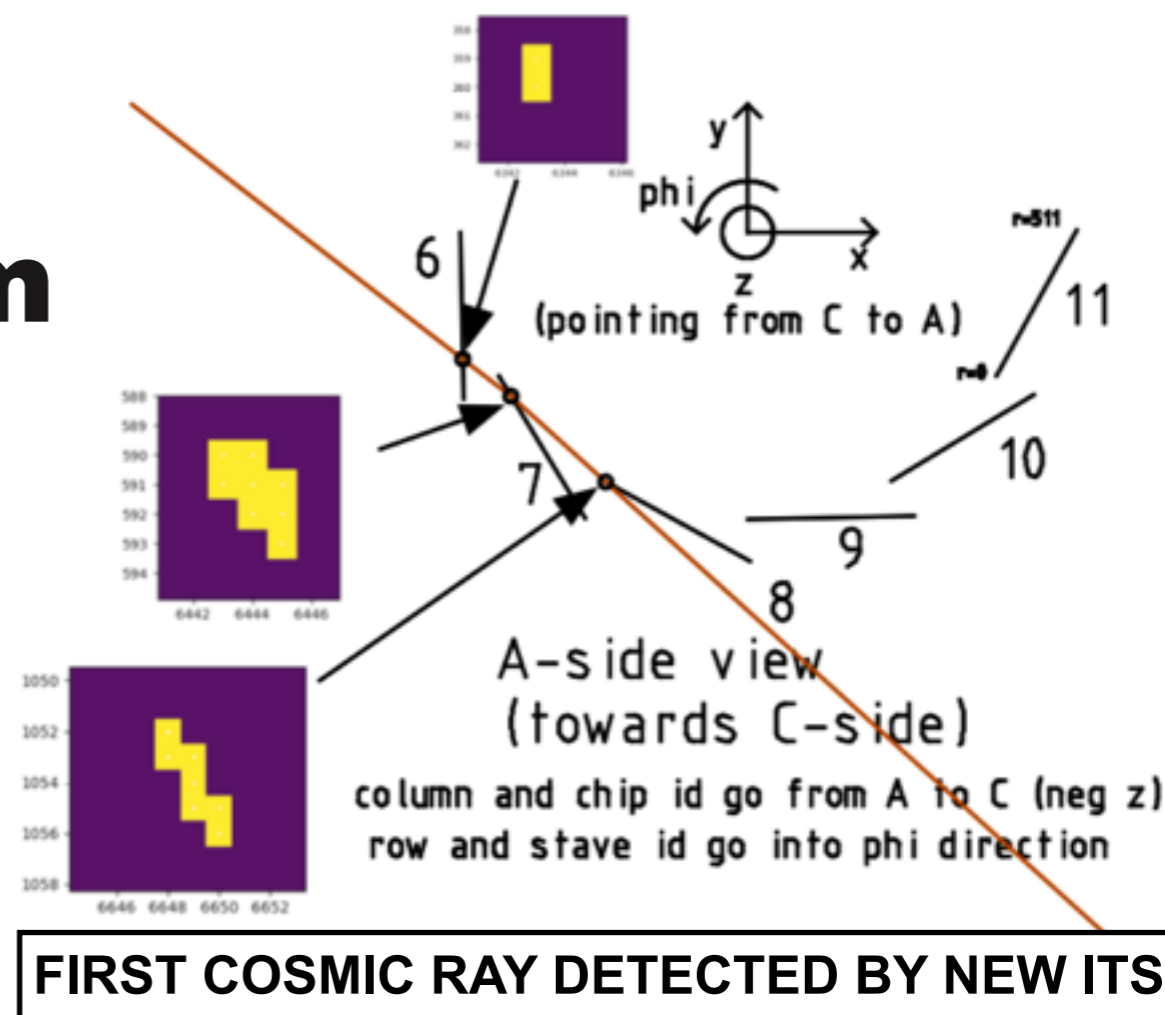


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Inner Tracking System upgrade

Construction and commissioning



Domenico Colella

Istituto Nazionale di Fisica Nucleare, Sezione di Bari
on behalf of the ALICE Collaboration

ALICE upgrade



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Physics motivations for the **Upgrade** → High precision measurements of rare probes over broad p_T range

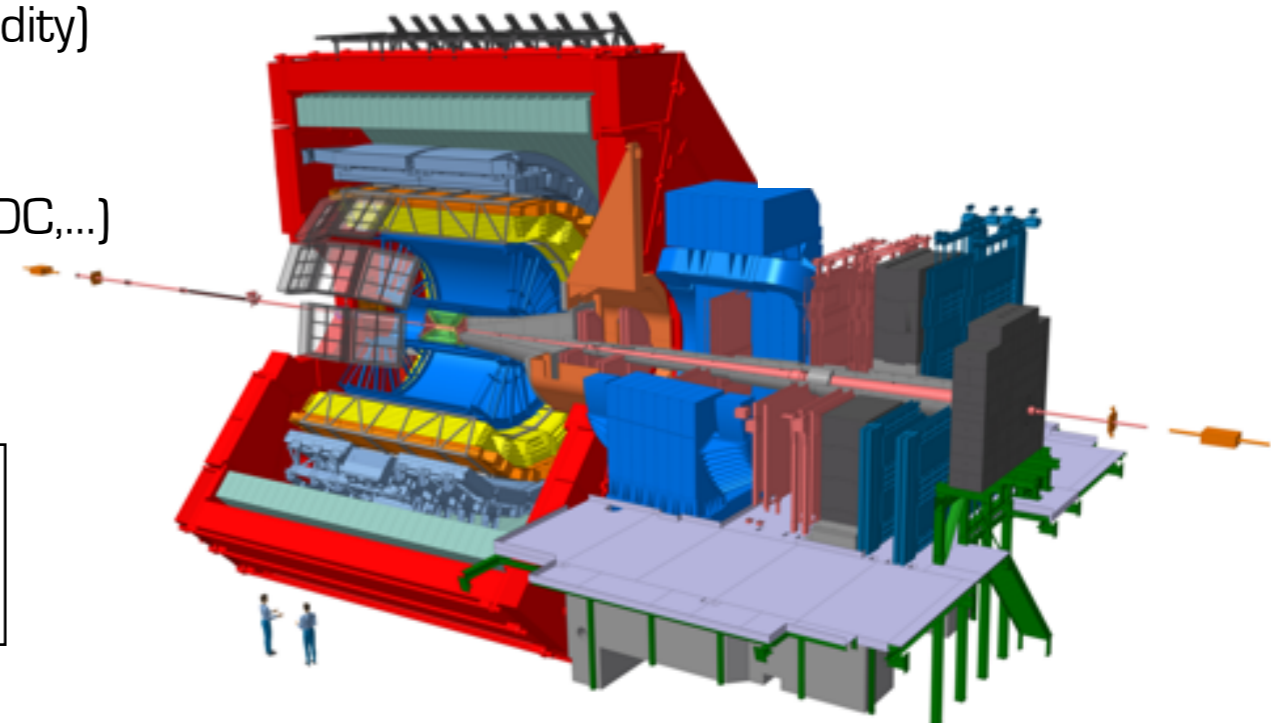
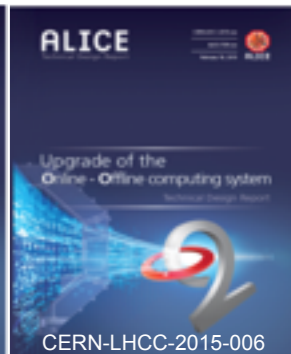
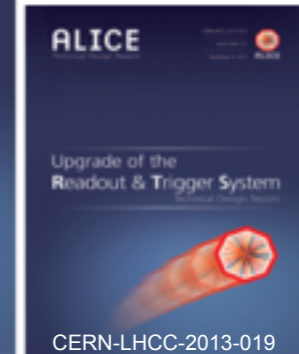
- » Heavy flavour mesons and baryons down to very low p_T
- » Charmonium and Bottomonium states
- » Low mass di-leptons
- » Light (anti-)nuclei and hyper-nuclei

Main upgrade requirements

- » Continuous read-out to fully exploit the LHC **50 kHz Pb–Pb interaction rate**
- » Improved tracking performance down to very low p_T

Upgrade strategy

- » New silicon trackers: **ITS** (mid-rapidity), MFT (forward rapidity)
- » New TPC read-out chambers (GEMs) and electronics
- » New Fast Interaction Trigger (FIT)
- » Fast read-out of other detectors (TOF, TRD, Muon arm, ZDC,...)
- » New Online plus Offline system (O^2 project)



G. MARTINEZ-GARCIA at SQM2017

https://indico.cern.ch/event/576735/contributions/2566943/attachments/1492972/2321904/GinesMARTINEZ_SQM2017.pdf

ITS upgrade - Improvements vs ITS (Run1/Run2)

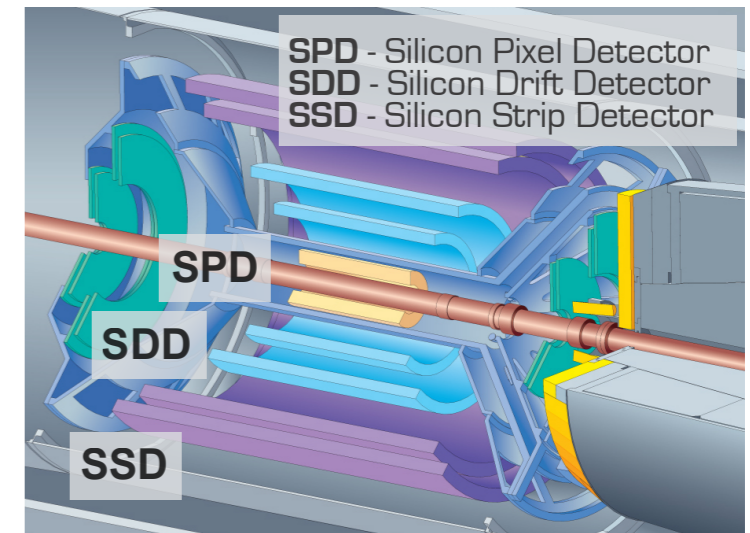


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ITS upgrade requirements

- » Improve impact parameter resolution
 - Reduce distance from IP to first layer → new beam pipe
 - Reduce material budget
 - Reduce pixel size
- » Improve tracking efficiency and p_T resolution at low p_T
 - Increase granularity → from 6 to 7 layers, all pixels
- » Increase read-out capabilities

ITS (Run1/Run2)

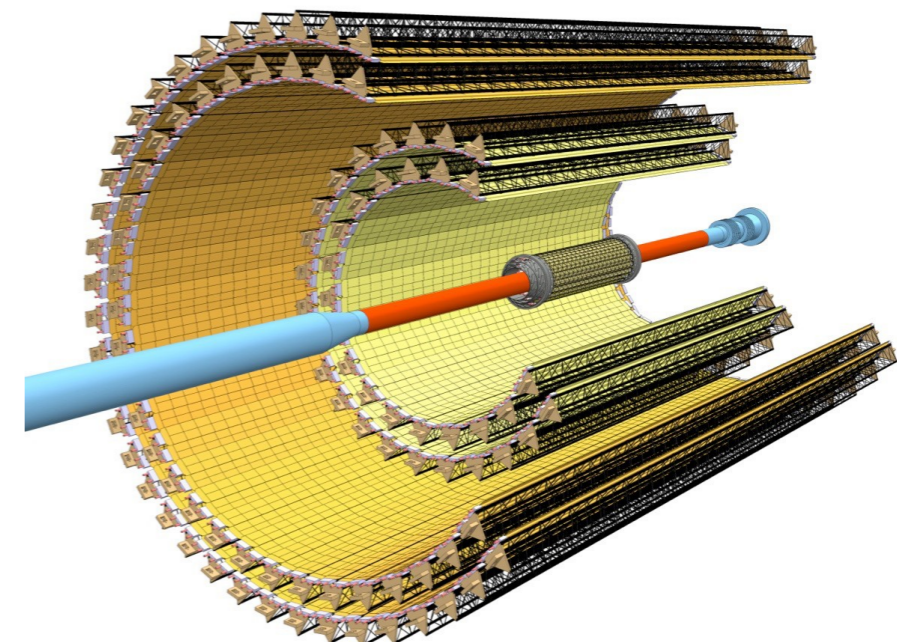


	ITS (Run1/Run2)	ITS Upgrade
Number of layers	6 (pixel, drift, μ strip)	7 (MAPS*)
Rapidity range	$ \eta < 0.9$	$ \eta < 1.3$
Material budget per layer	1.14% (SPD)	0.35% (IL)
Distance to interaction point	39 mm	22 mm
Pixel size	$50 \times 425 \mu\text{m}^2$	$29 \times 27 \mu\text{m}^2$
Spatial resolution	$12 \mu\text{m} \times 100 \mu\text{m}^*$	$5 \mu\text{m} \times 5 \mu\text{m}$
Max. readout speed Pb-Pb	1 kHz	100 kHz

* SPD

* Monolithic Active Pixel Sensors

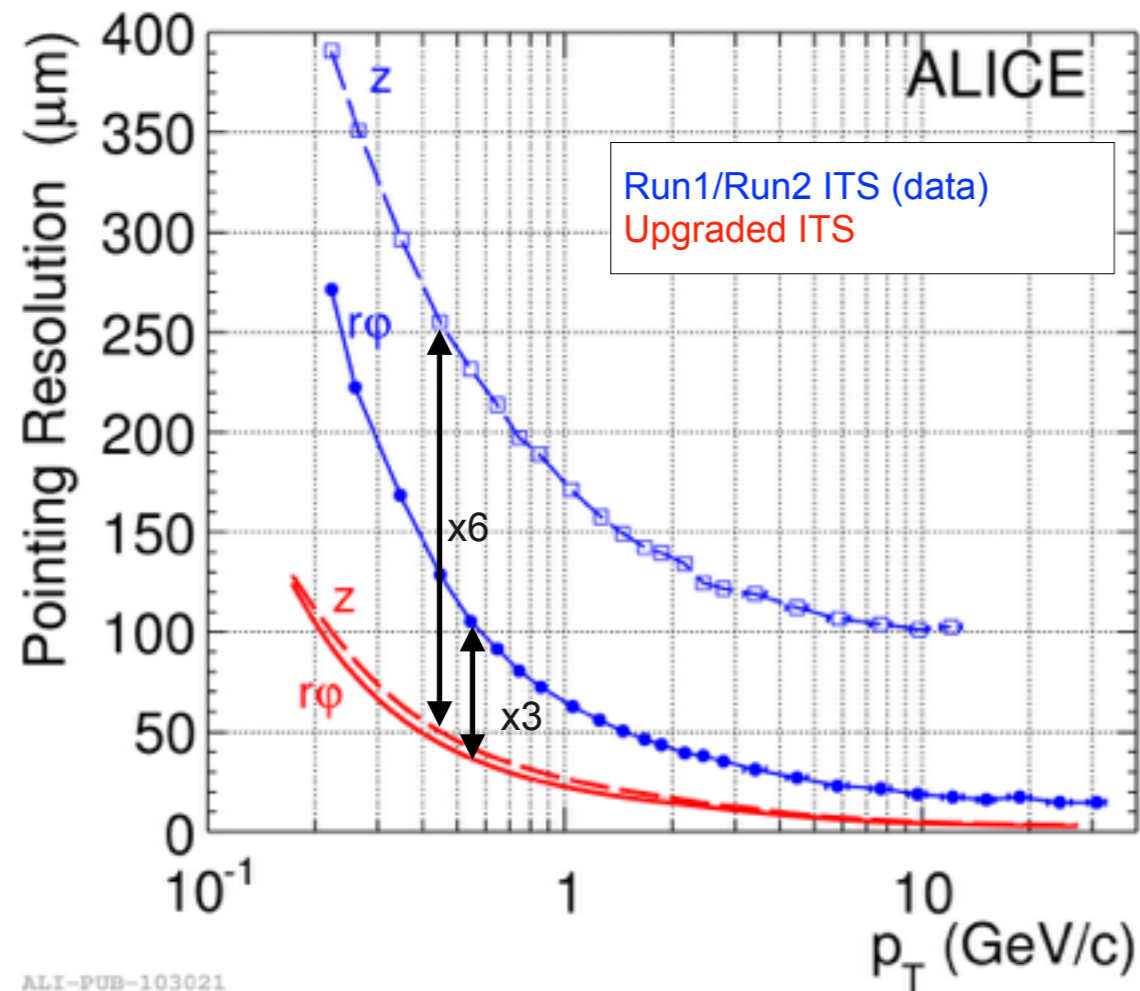
ITS Upgrade



ITS upgrade - Detector performance

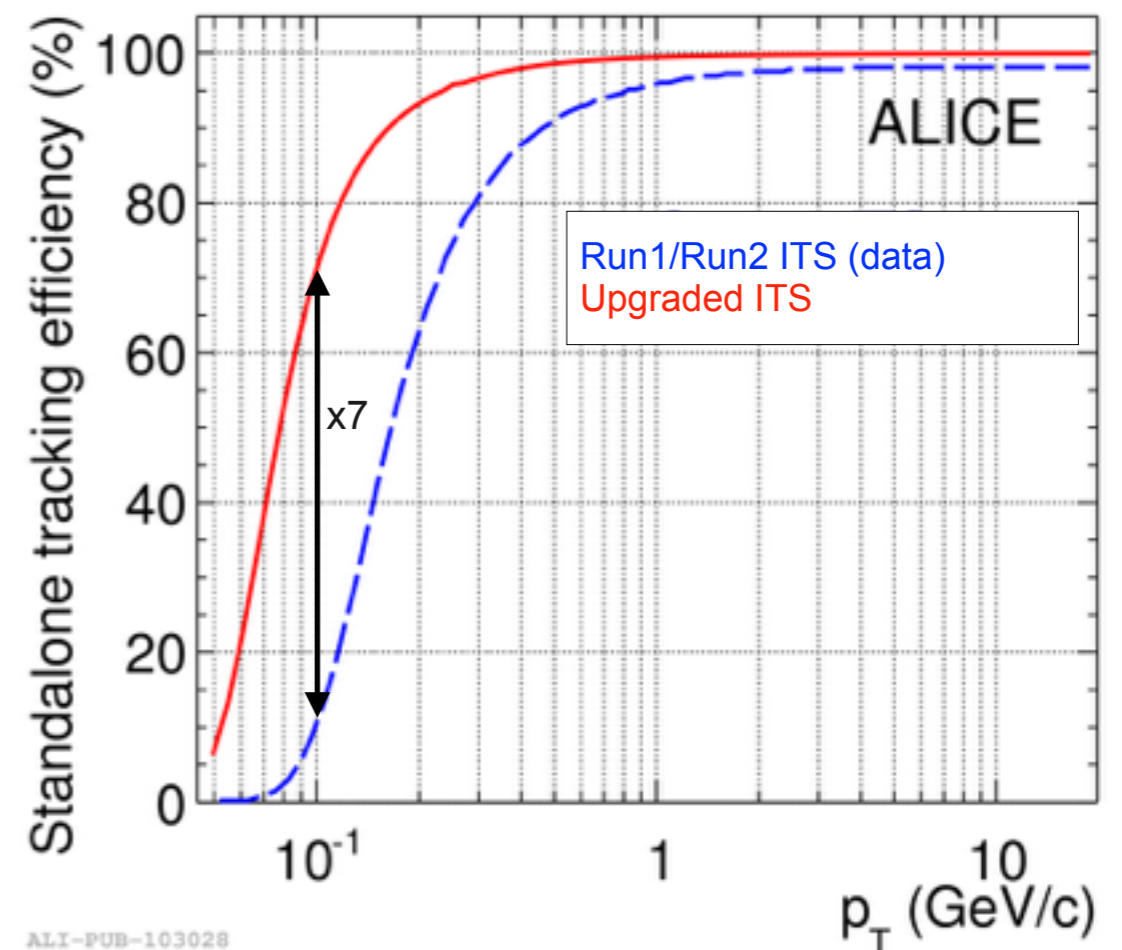


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- » Pointing resolution improved by
- 6 times in z direction for $p_T < 1$ GeV/c
 - 3 times in $r\phi$ direction for $p_T < 1$ GeV/c

» ITS standalone tracking efficiency significantly increased for $p_T < 1$ GeV/c

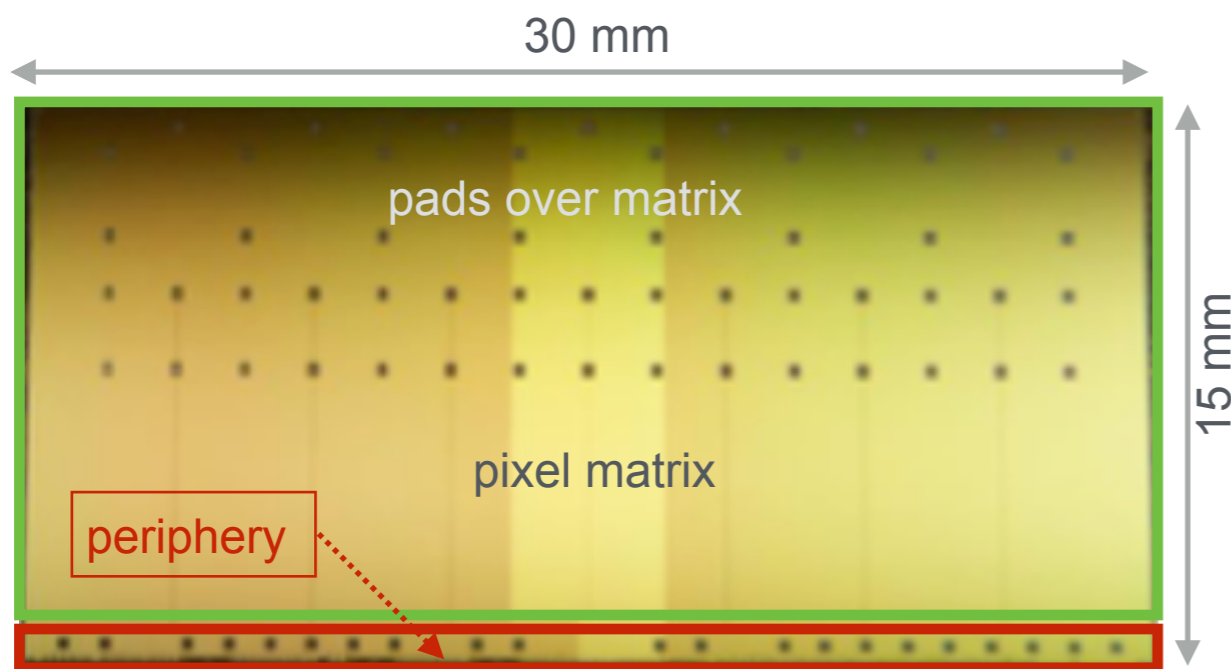




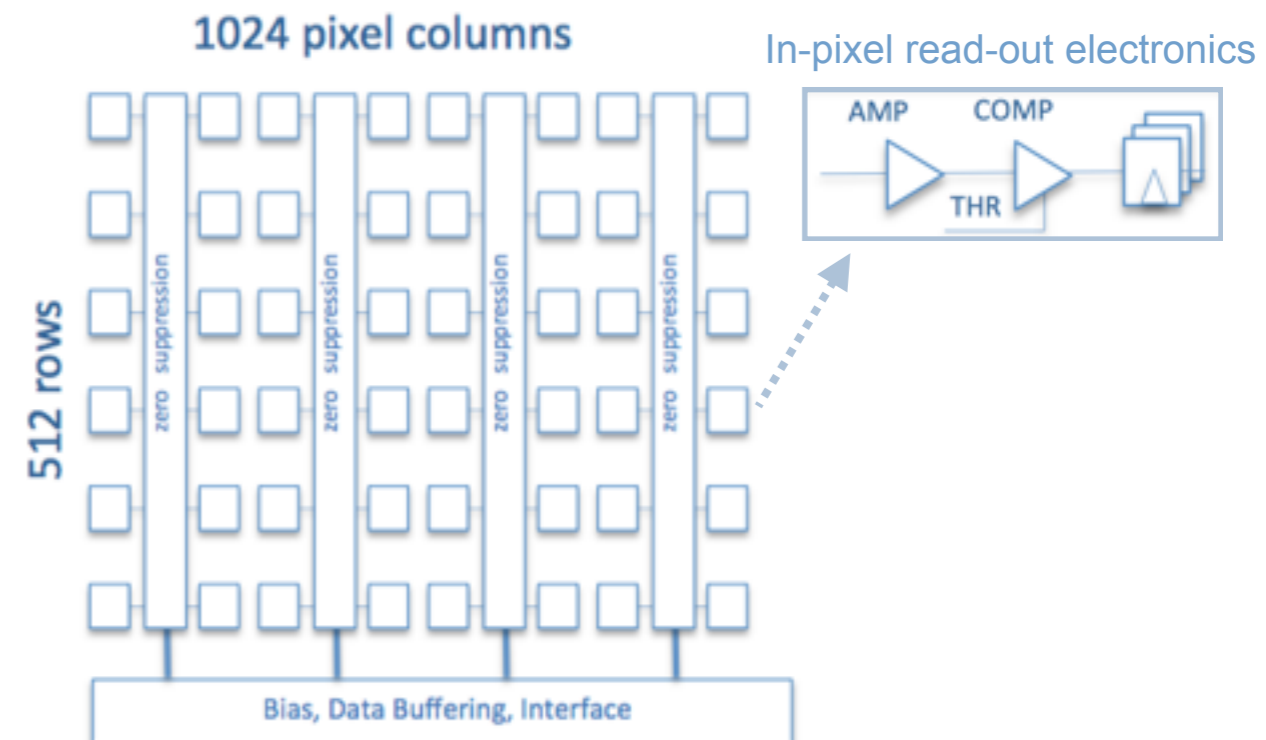
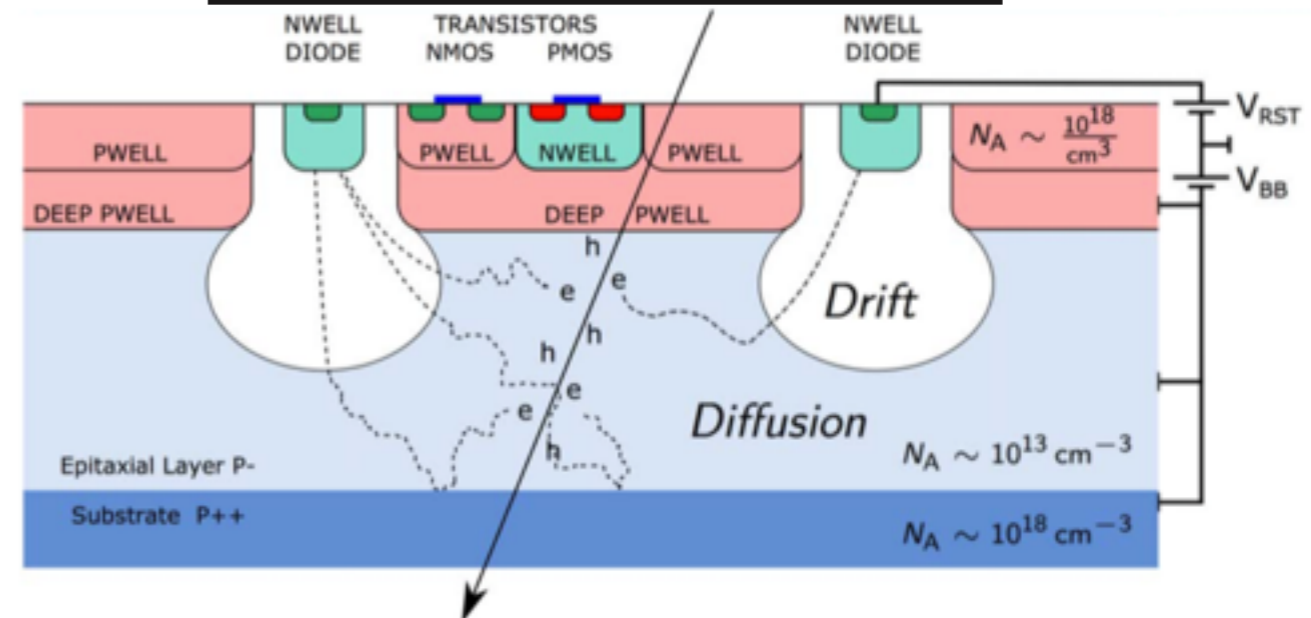
ITS upgrade - ALPIDE chip

Monolithic chip

- » Deep p-well layer → full CMOS in-pixel read-out circuit
- » Data buffering and configuration circuit in periphery
- » On-chip high speed data link (1.2 Gb/s)
- » Power consumption 40 mW/cm²
- » Irradiated chips (NIEL 1.7x10¹³ MeV n_{eq}/cm³) show large operational margin and chip-to-chip negligible fluctuations



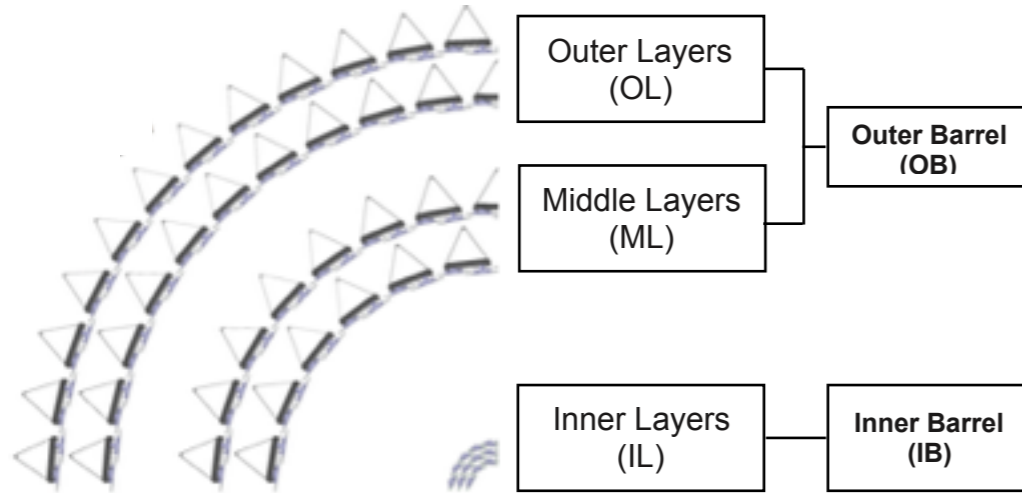
ALICE PIXEL DETECTOR



ITS upgrade - Layout and components



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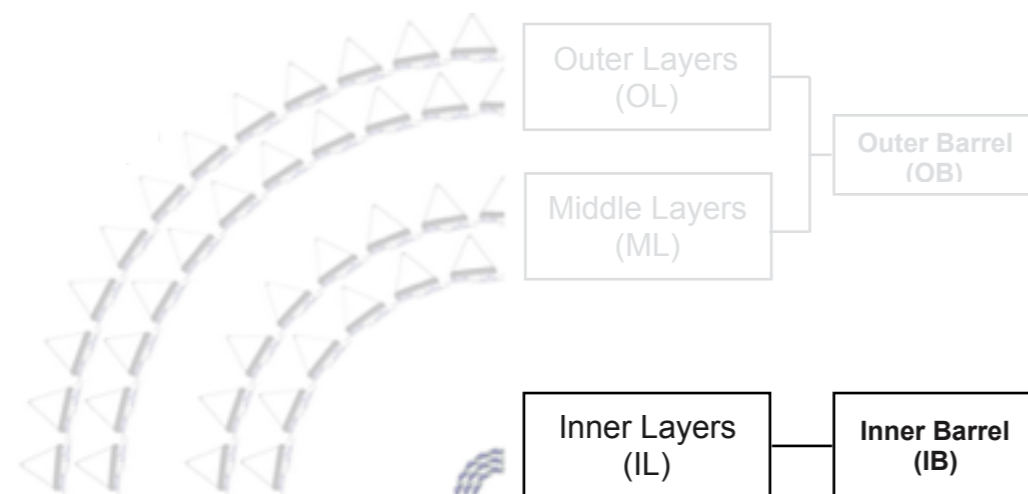
7-layer barrel geometry based on MAPS

- » Inner Barrel (**IB**) : 3 layers
- » Outer Barrel (**OB**) : 4 layers
- » r coverage: (min) 22 – (max) 394 mm
- » η coverage: (min) 1.3 – (max) 2.5
- » 12.6 Gigapixels
- » Total active area $\sim 10 \text{ m}^2$



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ITS upgrade - Layout and components

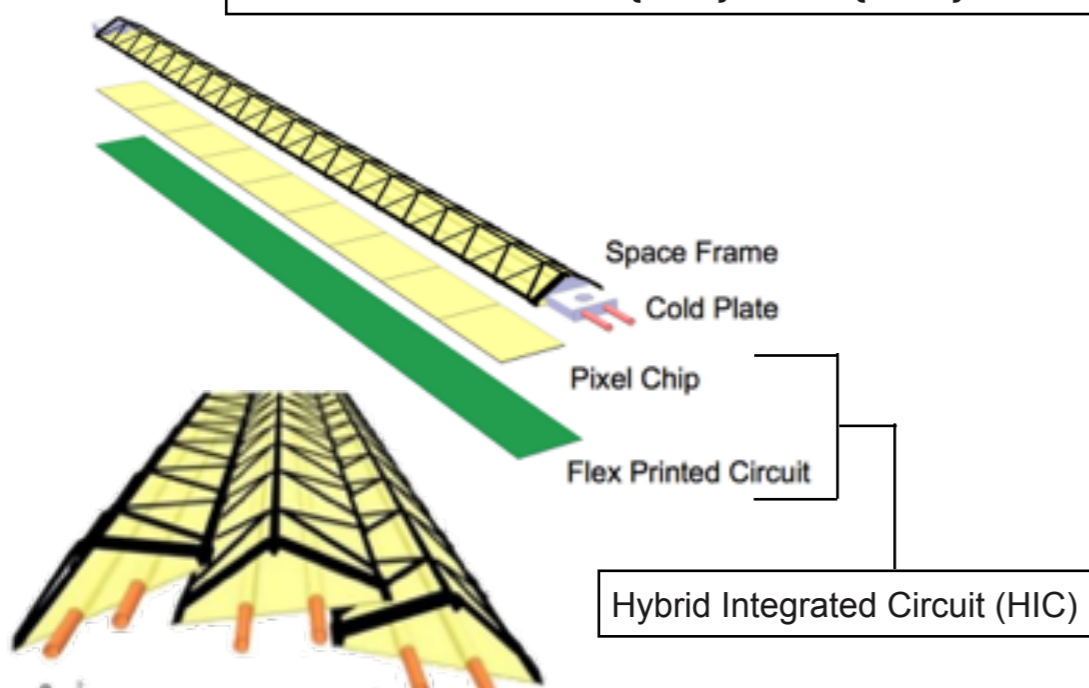


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Inner Barrel

- » 48 staves
- » 9 ALPIDE chips on 1 row per stave
- » chip thickness: $50 \mu\text{m}$
- » stave length: 290 mm
- » distance from IP: (min) 22 – (max) 42 mm

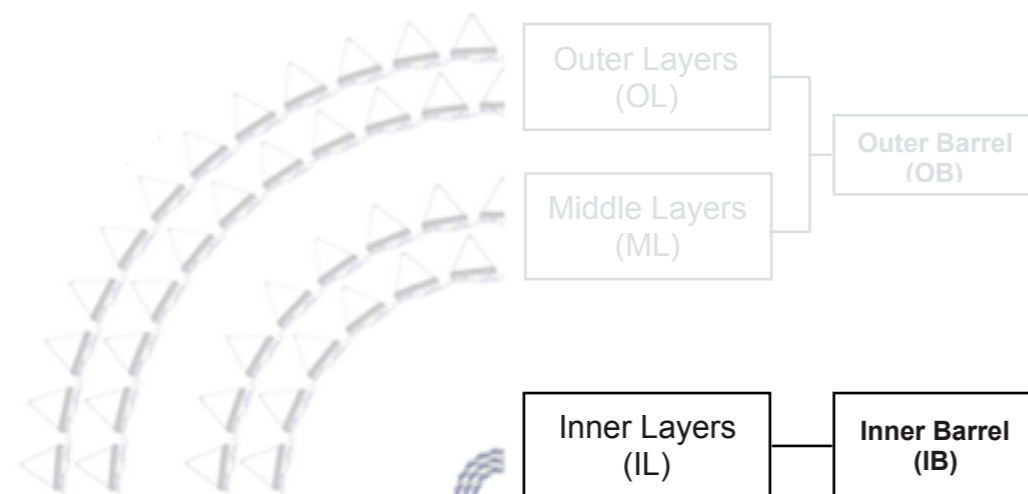


Tilted staves with overlap



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ITS upgrade - Layout and components

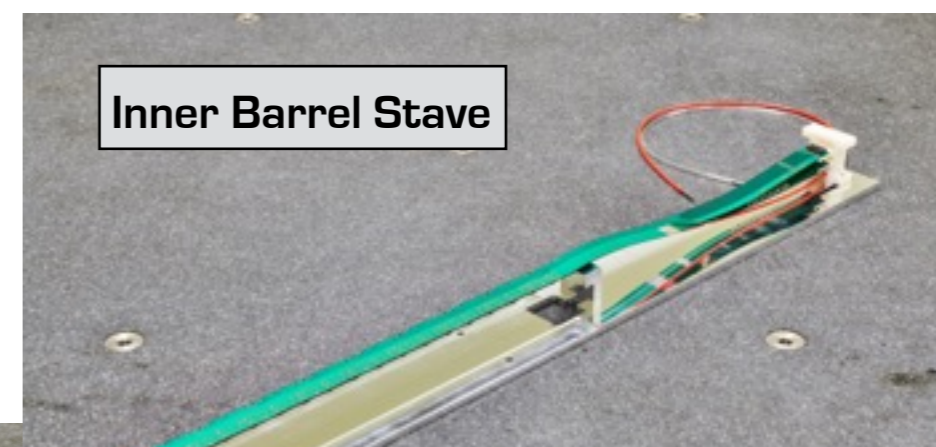
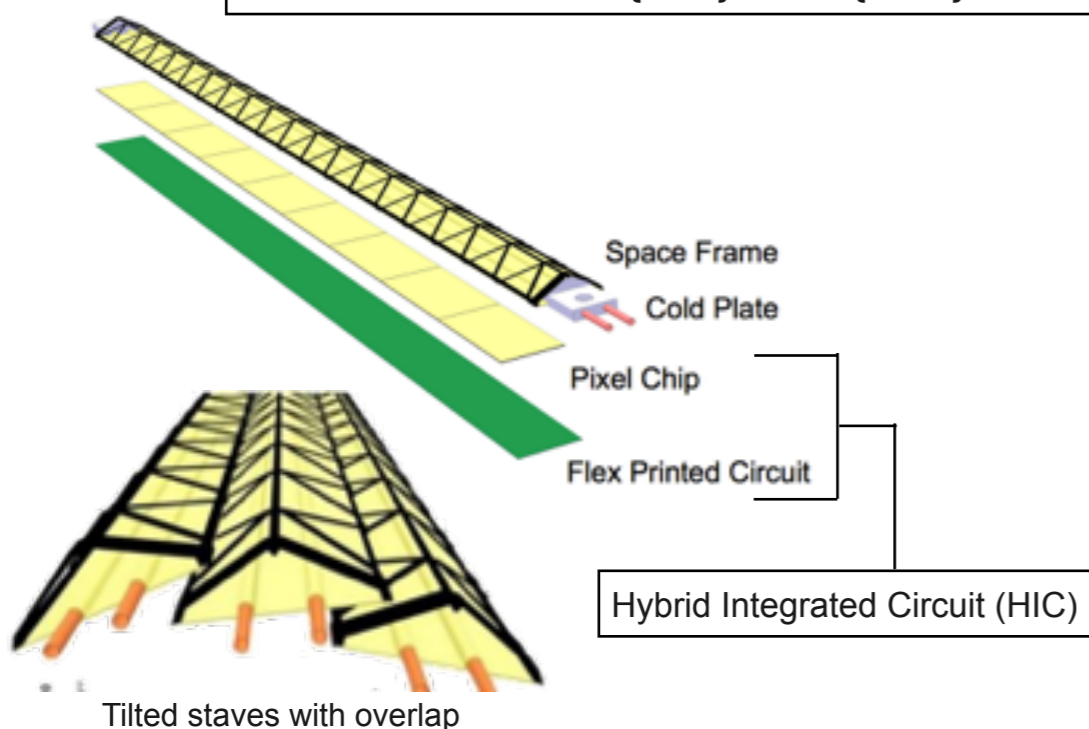


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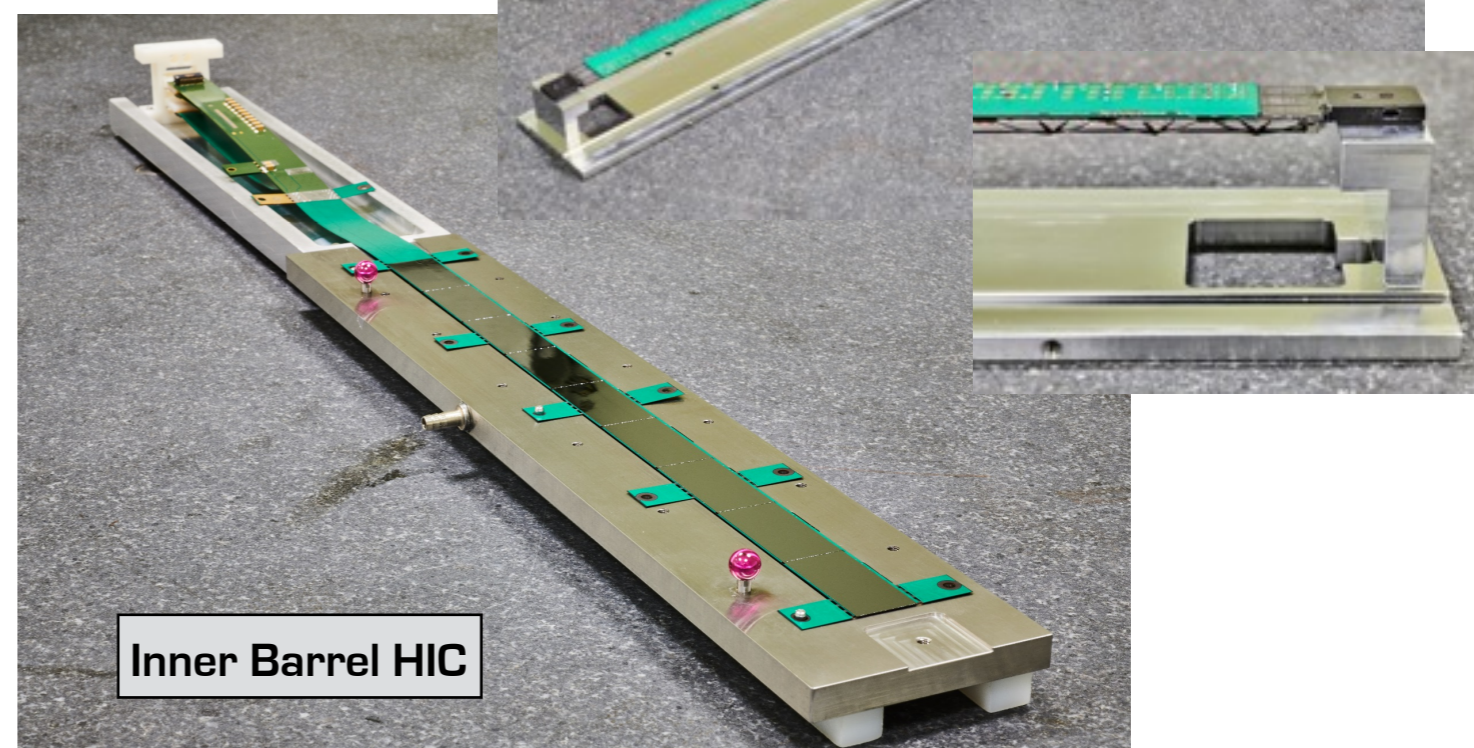
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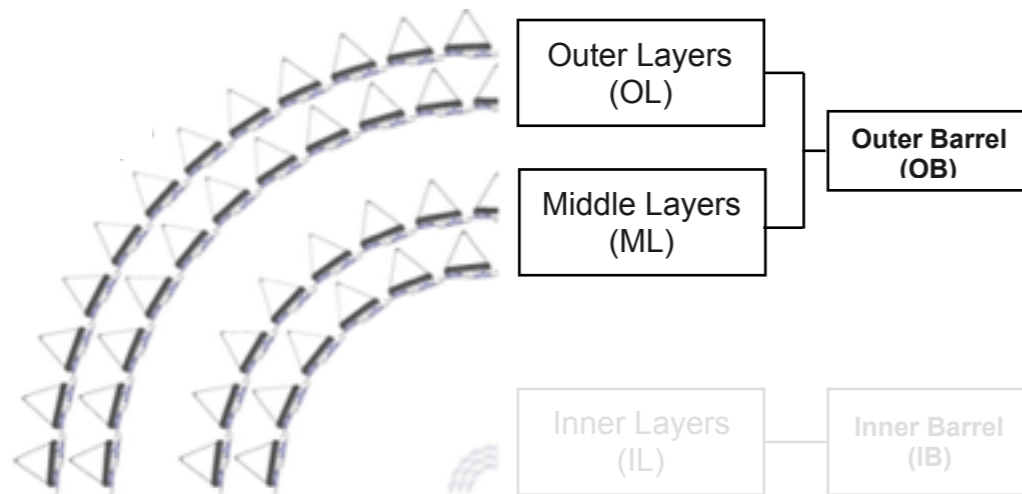


Inner Barrel Stave



Inner Barrel HIC

ITS upgrade - Layout and components



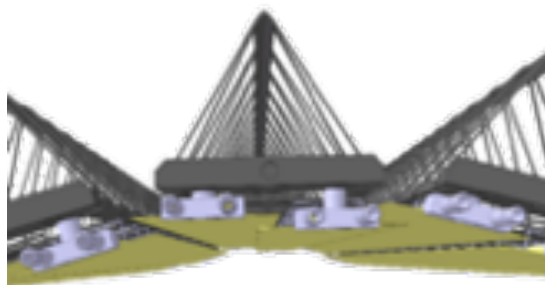
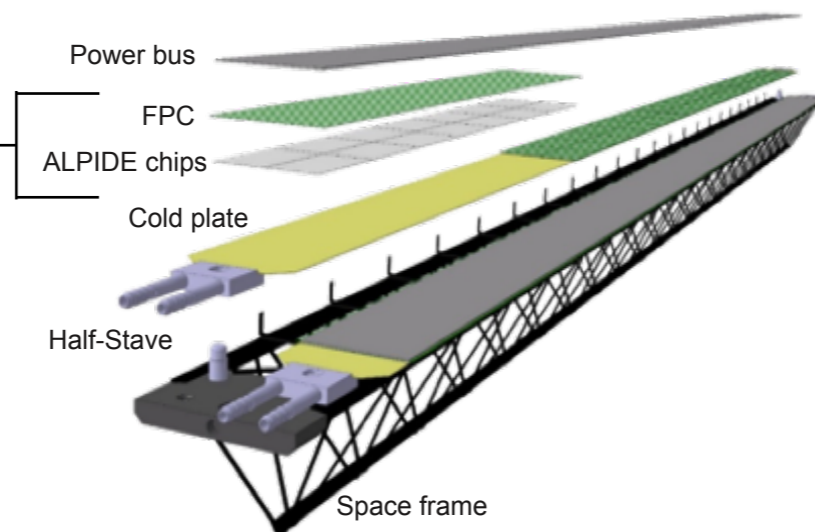
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Outer Barrel

- » 54 staves in ML + 90 staves in OL
- » ML: 56 ALPIDE chips on 2 rows per stave in ML
- » OL: 98 ALPIDE chips on 2 rows per stave in OL
- » chip thickness: $100 \mu\text{m}$
- » stave length: 843 – 1473 mm
- » distance from IP: (min) 194 – (max) 394 mm

Hybrid Integrated Circuit (HIC)

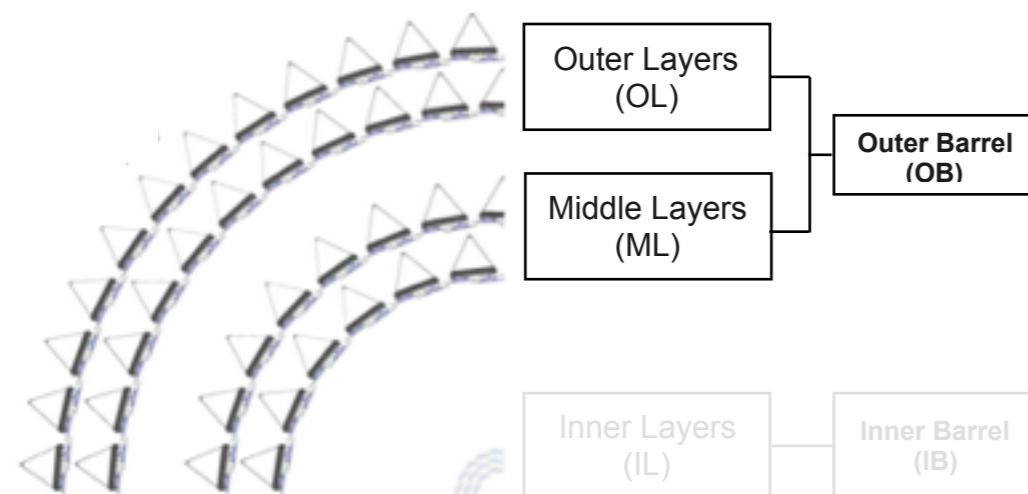


Tilted staves with overlap



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ITS upgrade - Layout and components



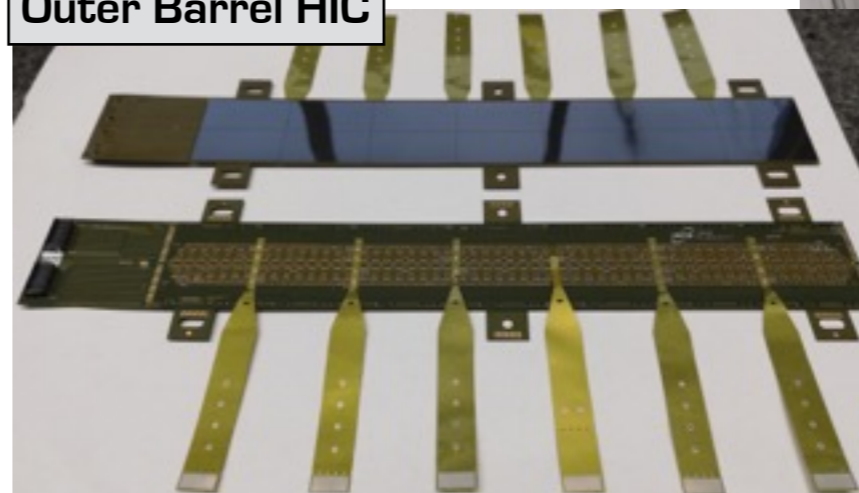
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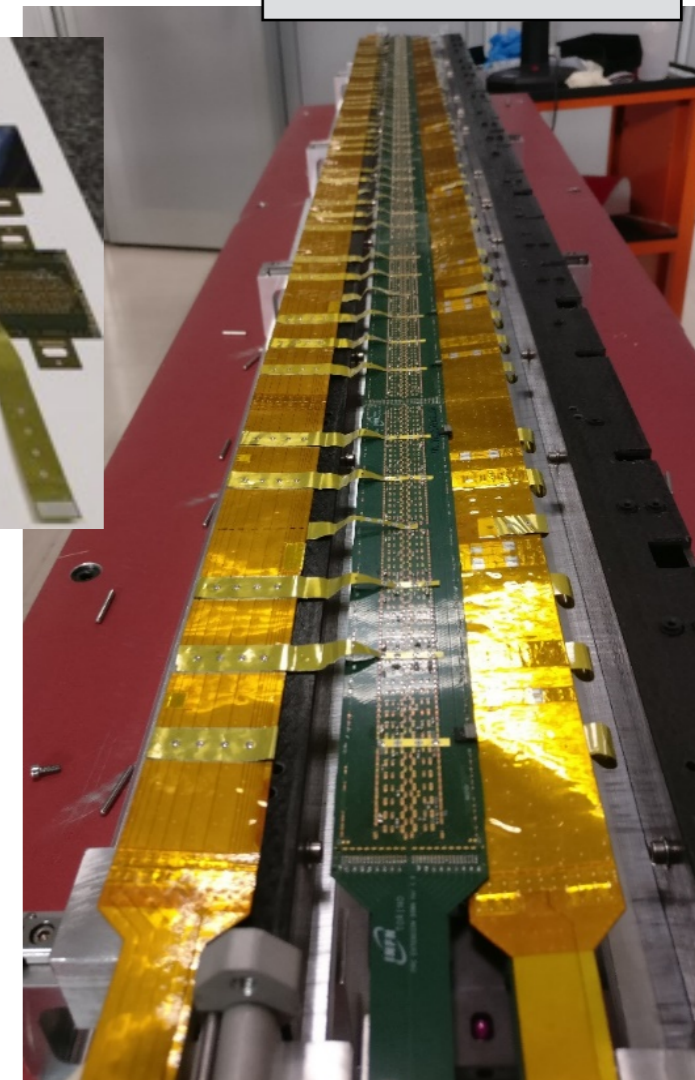
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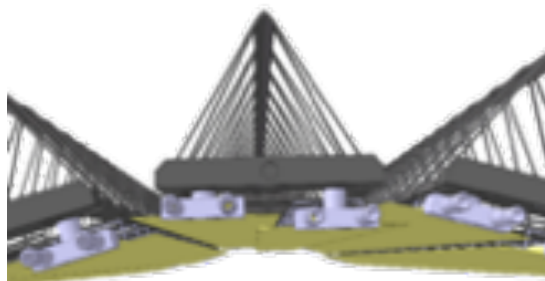
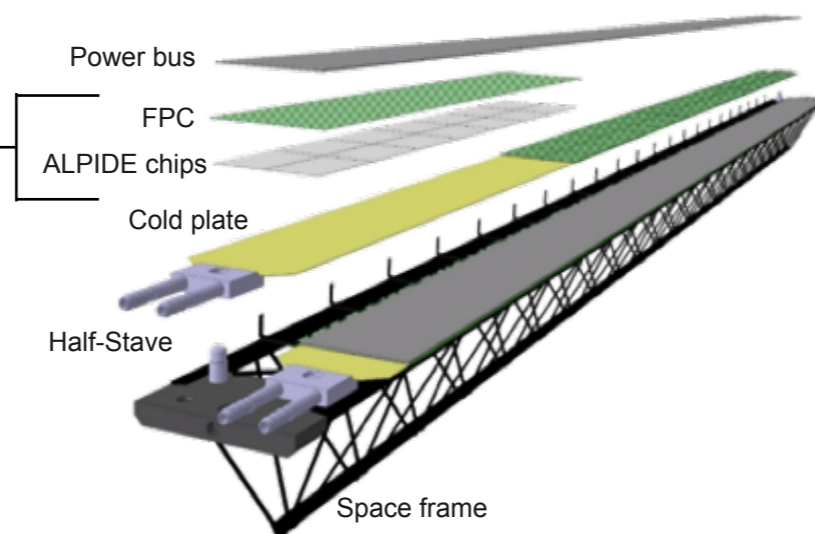
Outer Barrel HIC



Outer Barrel Staffe



Hybrid Integrated Circuit (HIC)

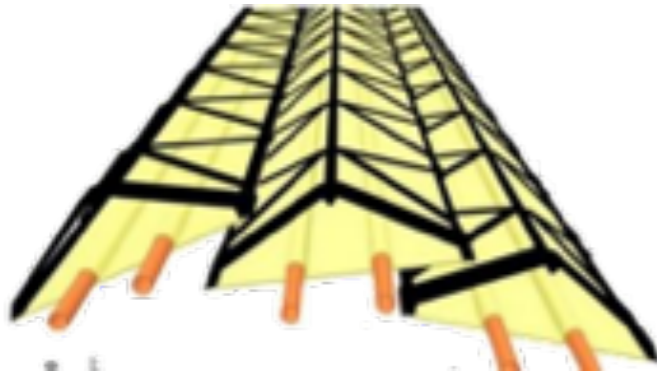


Tilted staves with overlap

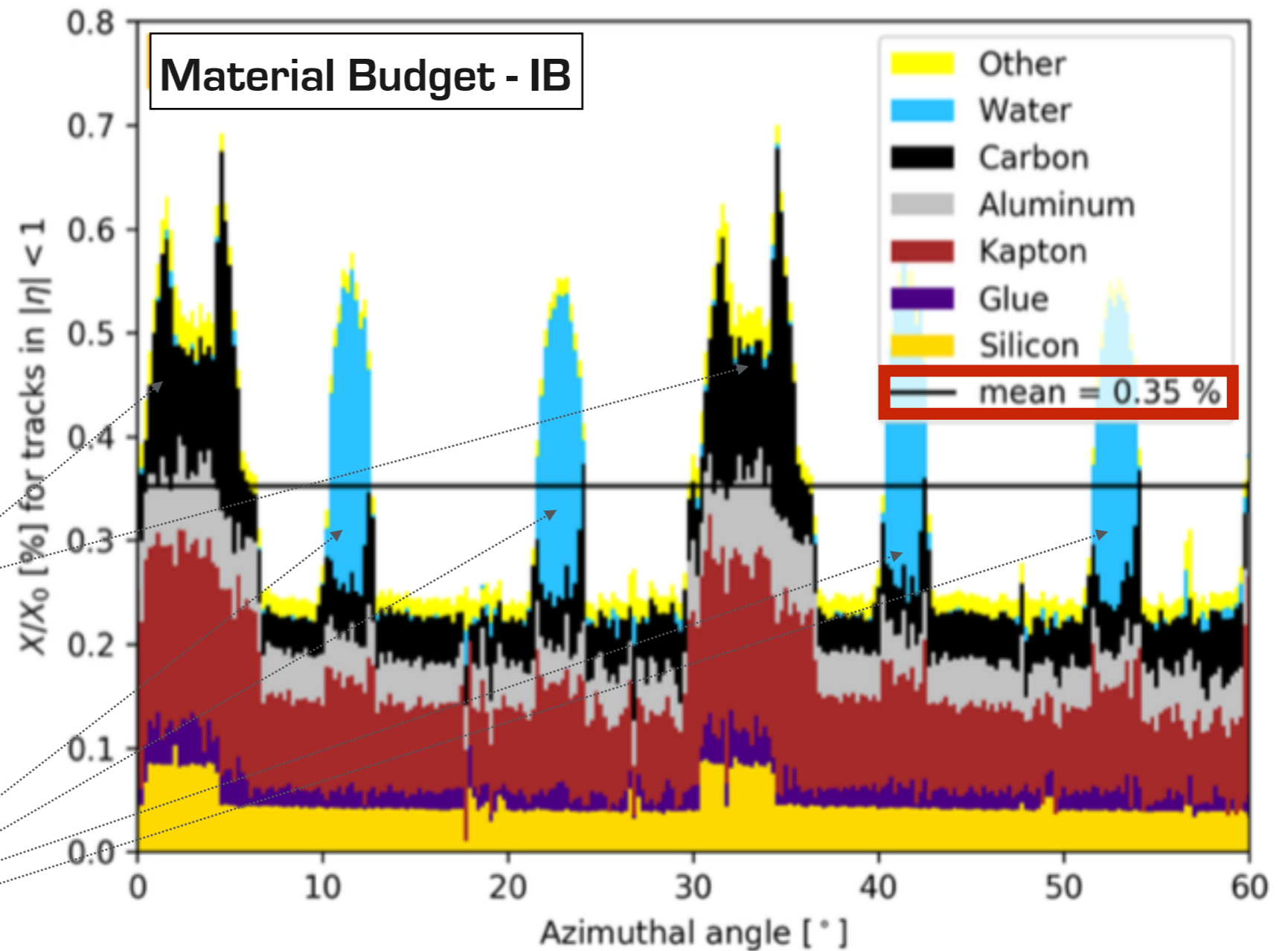
ITS upgrade - Layout and components



ALICE

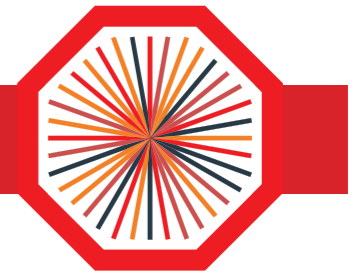


Tilted staves with overlap



HICs overlap

Cooling pipes



ITS upgrade - Component production status

ALPIDE chips

» Institutes:

50 μm : CERN

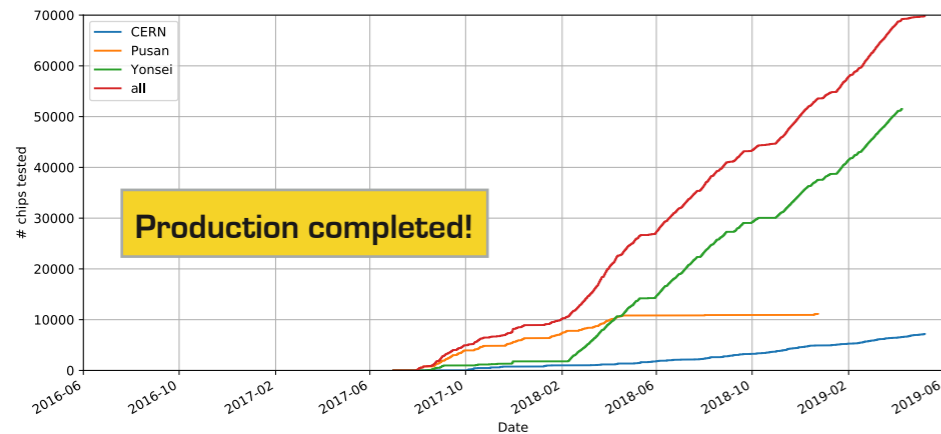
100 μm : Yonsei, Pusan

» Total # of chips tested: ~70000

» Total # of wafers: ~1700

» Total yield: 63.7%

» Series test ended in mid 2018

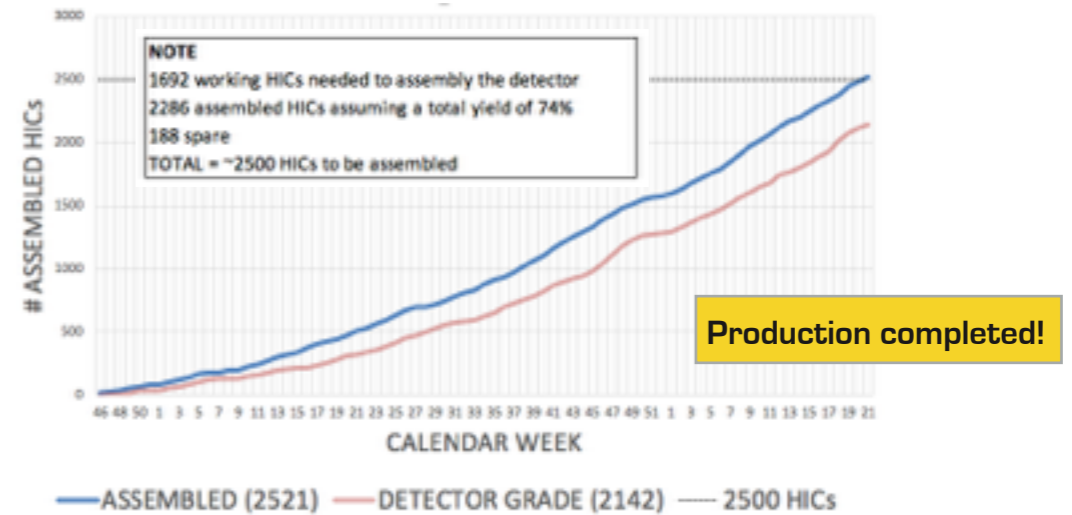


Outer Barrel HICs and Staves

» HIC institutes:

Bari (IT), Liverpool (UK), Pusan (KR), Strasbourg (FR), Wuhan (CN), Trieste (IT)

» ~2500 HICs assembled with a yield of 85%

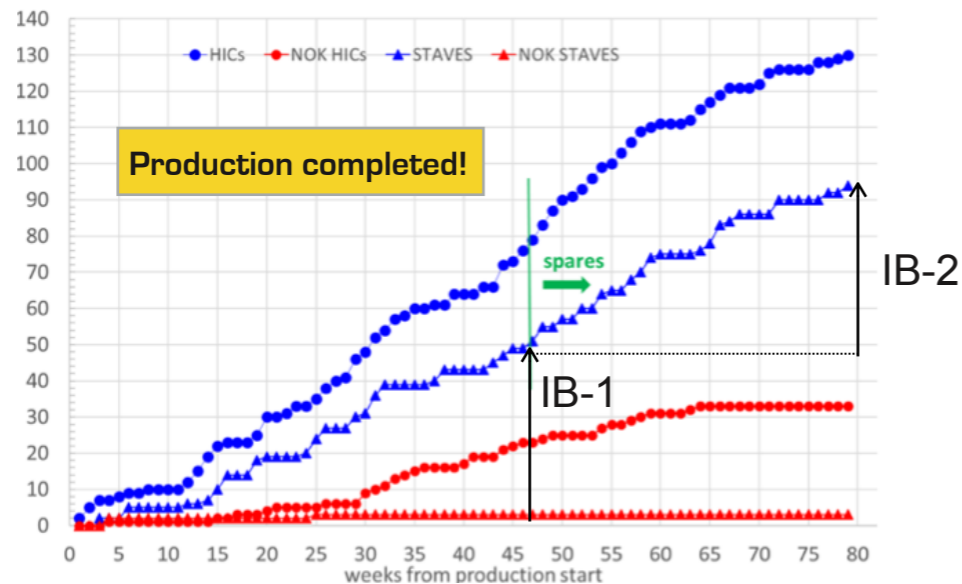


Inner Barrel HICs and Staves

» Institutes: CERN

» 95 staves assembled with a yield of 73%

» Enough for 2 fully working copies of IB



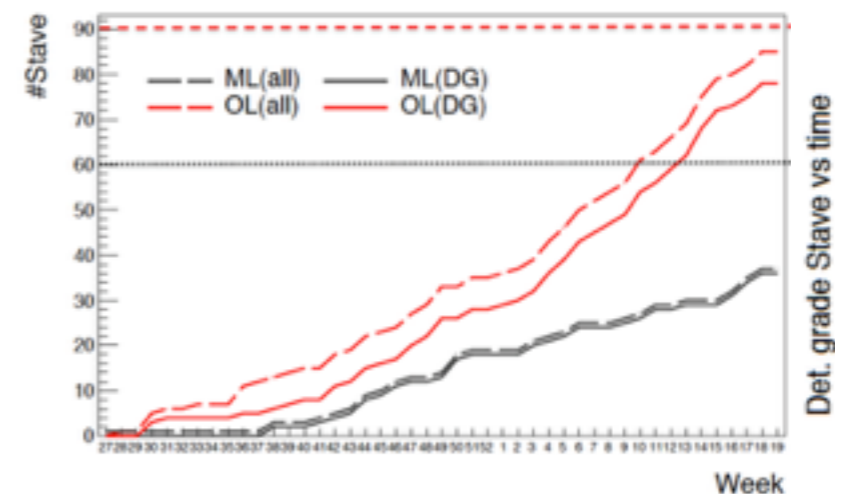
» Stave institutes:

Berkeley (US), Daresbury (UK), Frascati (IT), Nikhef (NL), Turin (IT)

» Yield above 90%

» OL stave production almost completed

» ML stave production will end by September 2019



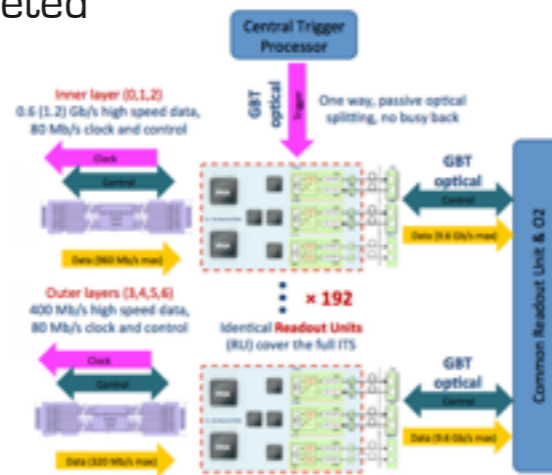


ITS upgrade - Component production status

Readout electronics

- » Institutes: Austin (US), Bergen (NO), CERN, Nikhef (ND), Padova (IT)
- » 192 FPGA based RUs, operating in a mild radiation environment (<10 krad, $<10^{12}$ 1 MeV n_{eq})
- » Board production completed
- » Functional test ongoing

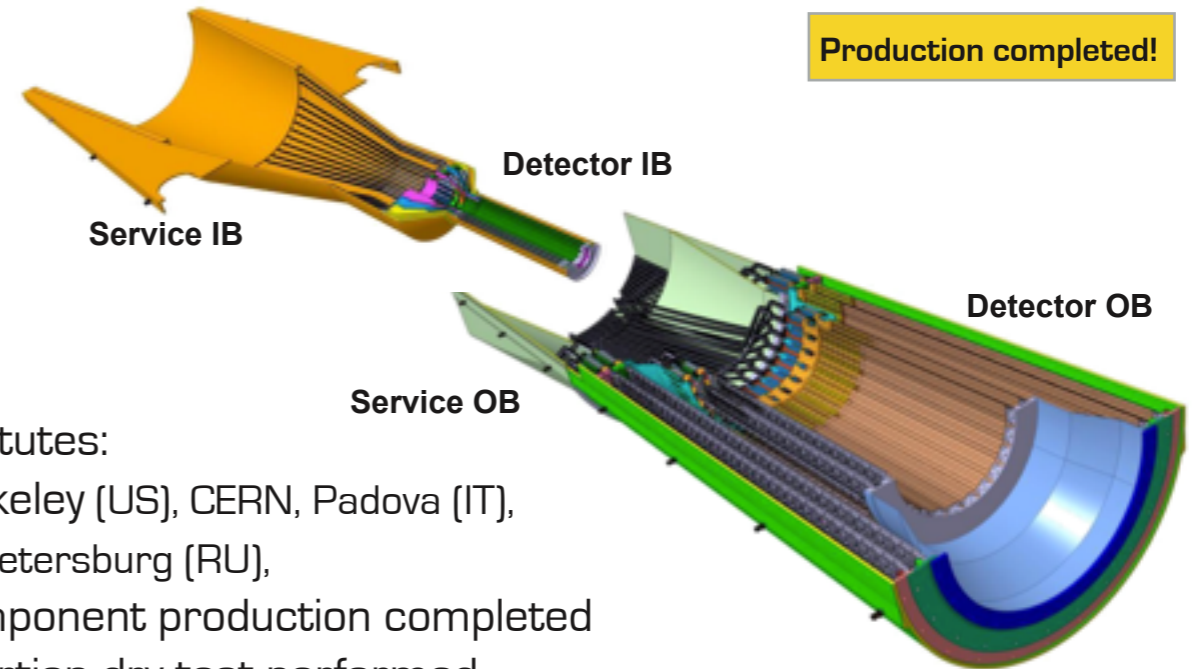
Production completed!



Support structures

- » Institutes: Berkeley (US), CERN, Padova (IT), St. Petersburg (RU)
- » Component production completed
- » Insertion dry test performed

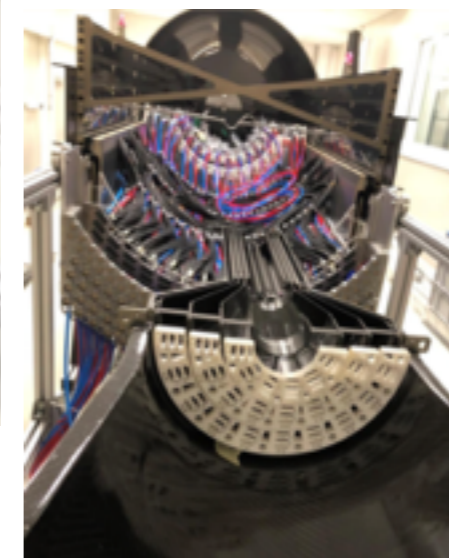
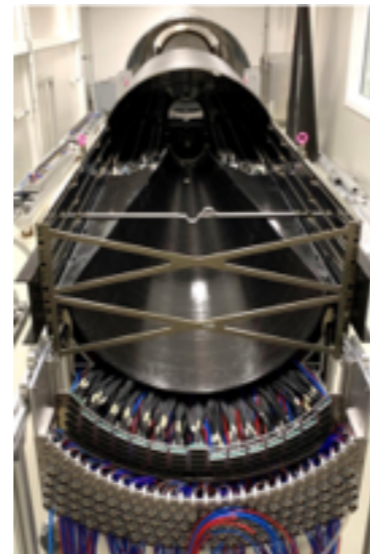
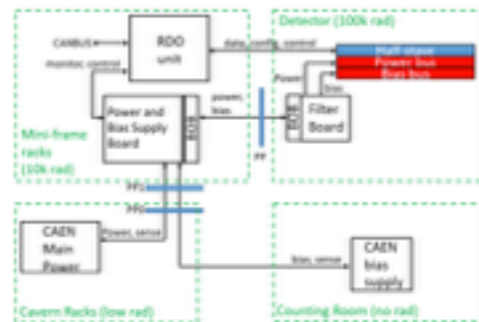
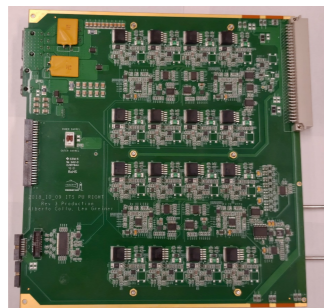
Production completed!

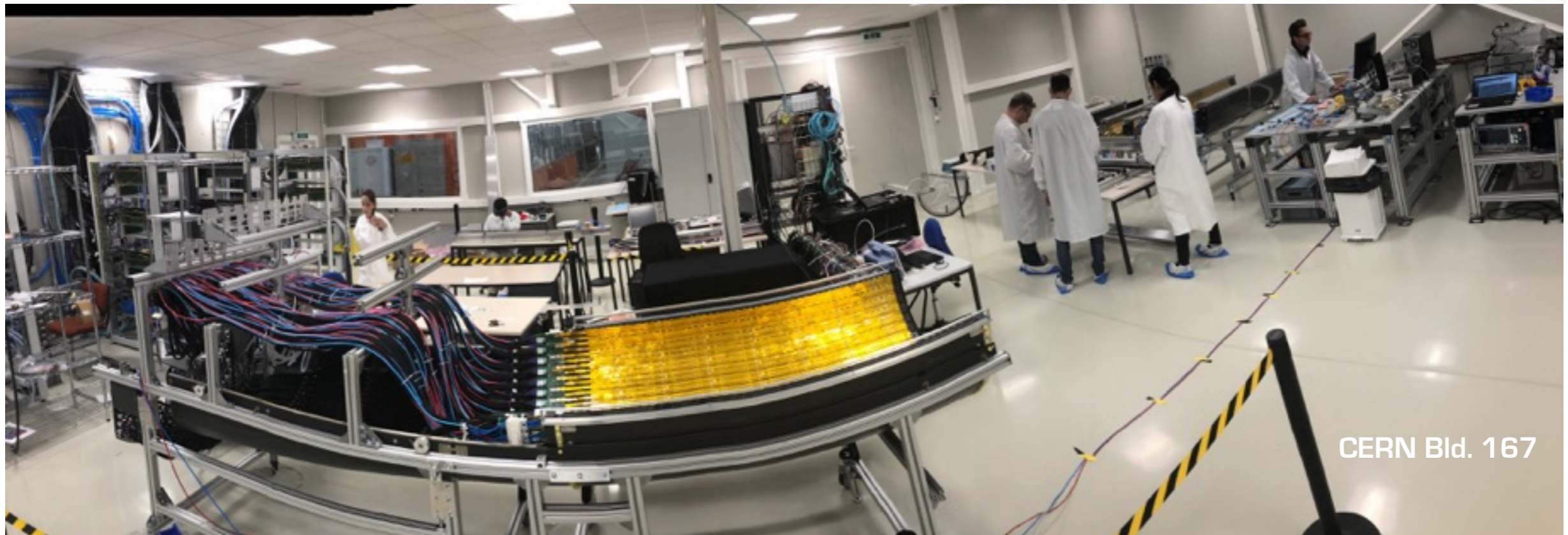


Power System

- » Institute: Berkeley (US)
- » CAEN powering modules available and in use in commissioning setup
- » Power board production completed
- » Functional test ongoing (until July 2019)

Production completed!





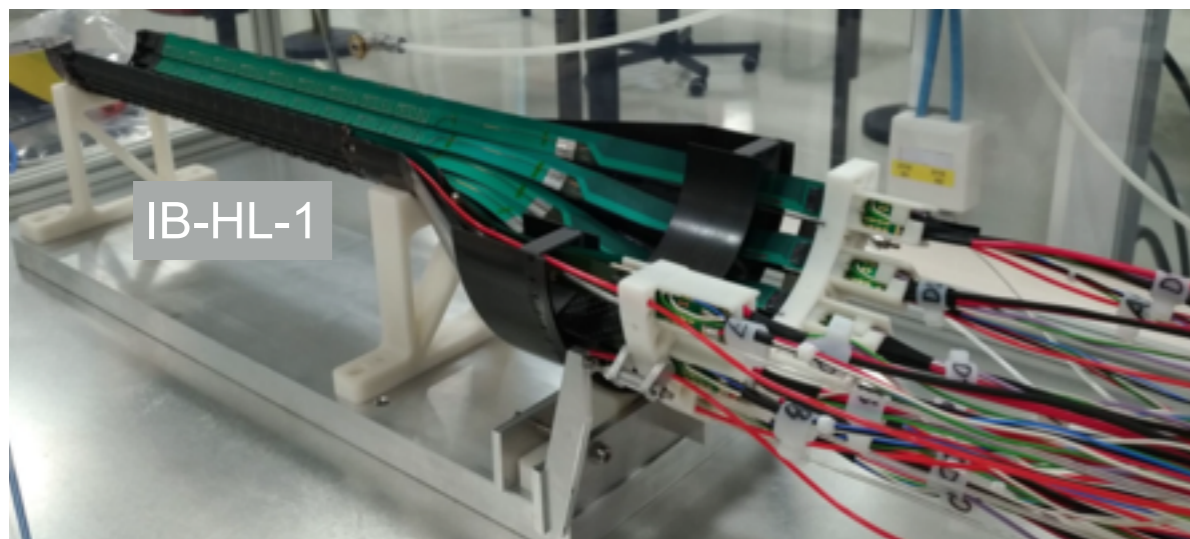
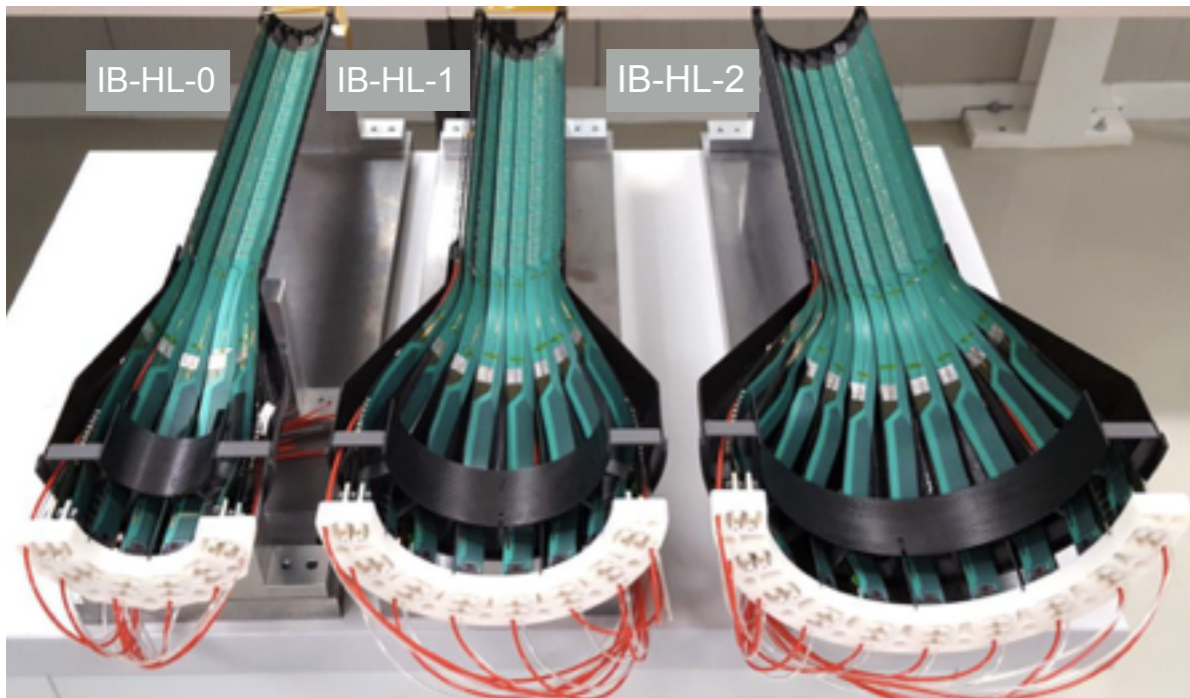
- » Fully equipped clean-room at CERN (Bld. 167) for layer assembly and commissioning
 - **Same backend system that will be used in the experiment (Cooling plant, Power and Read-out racks, Trigger and DAQ system)**
- » Layer assembly proceeds with the availability of staves (Outer Barrel)
- » DCS and DAQ systems: development of full functionalities ongoing
- » Commissioning before installation
 - » continuous operation 24/7
 - » data taking with cosmic rays and calibration scans
- » Fully automatised data quality control flow under preparation

ITS upgrade - Assembly and commissioning

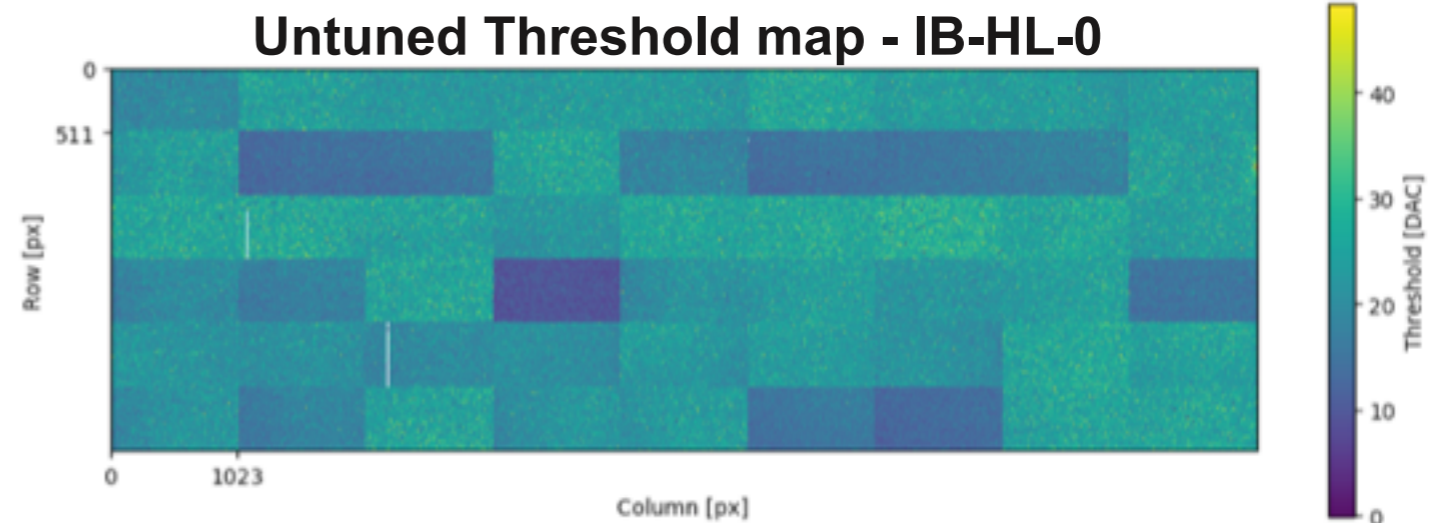
Inner Barrel



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- » All staves and mechanical supports available
- » IB-HL-0: able to read out all staves
 - » Final powering and read-out chain
- » IB-HL-1: fully connected to electronics and under test
- » IB-HL-2 : connection under preparation
- » Remaining HLs will follow with the availability of RUs
- » Commissioning ongoing of IB-HL-0

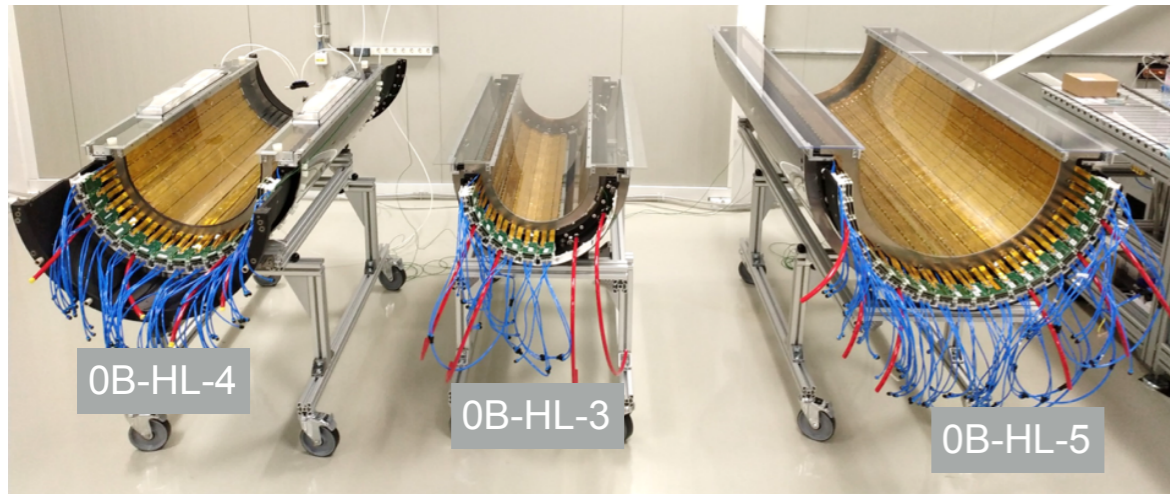


ITS upgrade - Assembly and commissioning

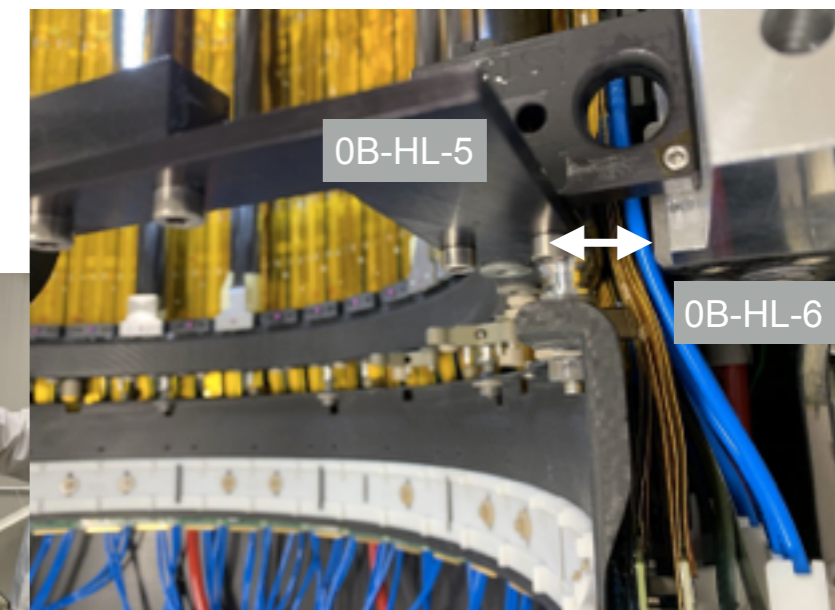
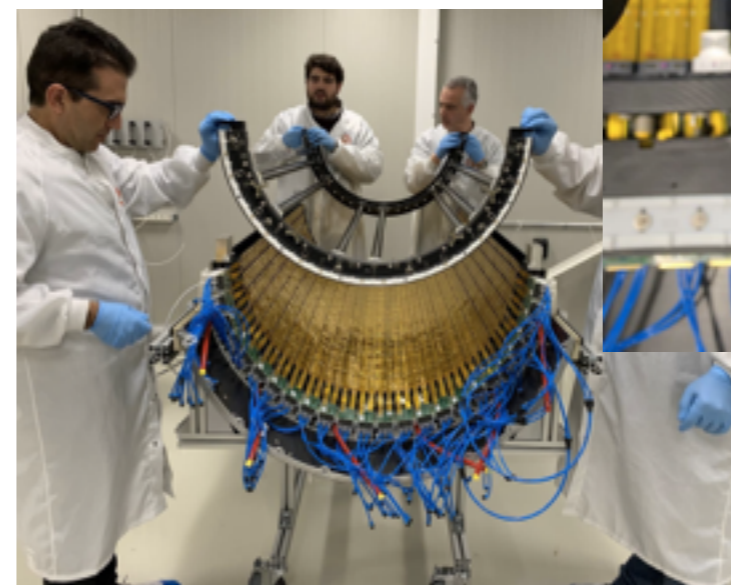
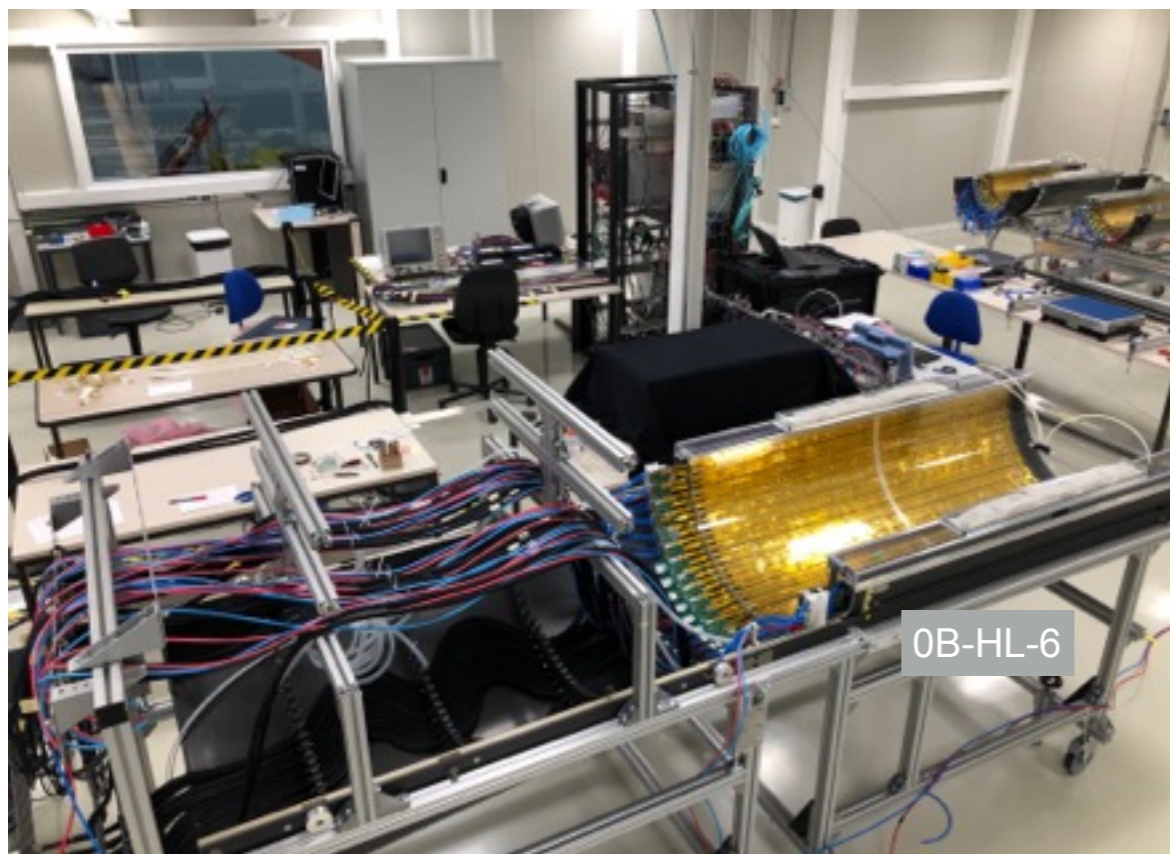
Outer Barrel



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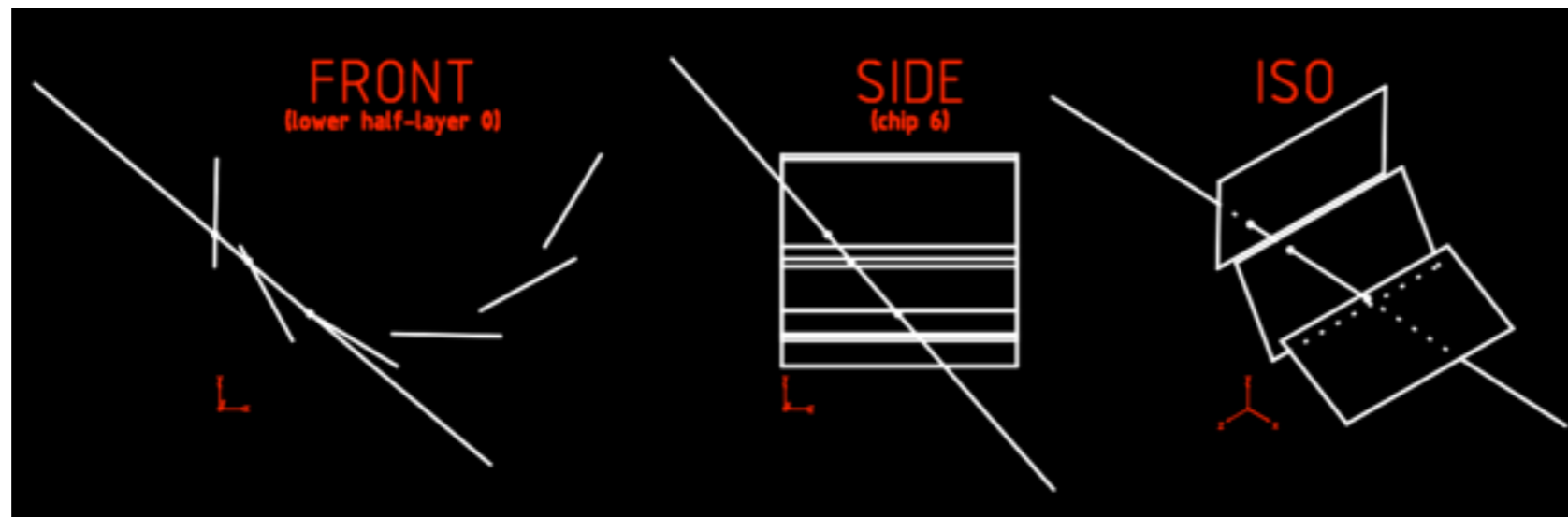
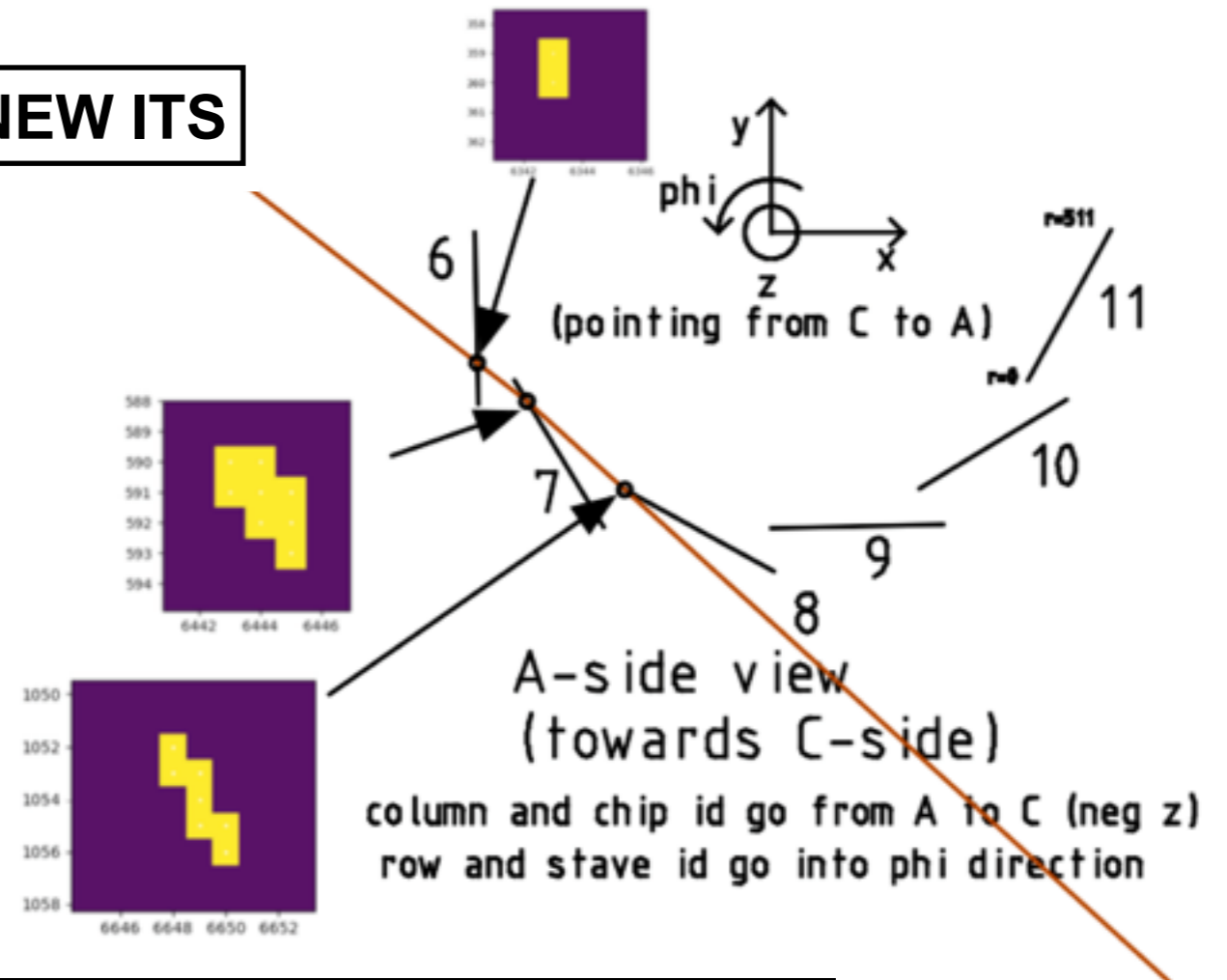
- » Staves assembled on following half-layers
 - » OB-HL-3 → Integration ongoing
 - » OB-HL-4 → **Completed!**
 - » OB-HL-5 → **Completed!**
 - » OB-HL-6 → **Completed!**
- » Cabling ongoing on OB-HL-6
 - » Next HL to be included in the commissioning





FIRST COSMIC RAY DETECTED BY NEW ITS

- » First reconstructed cosmic ray track in the IB-HL-0
- » Thanks to the overlap between adjacent staves
- » Three aligned pixel clusters observed in staves 6, 7 and 8 as shown in the figures



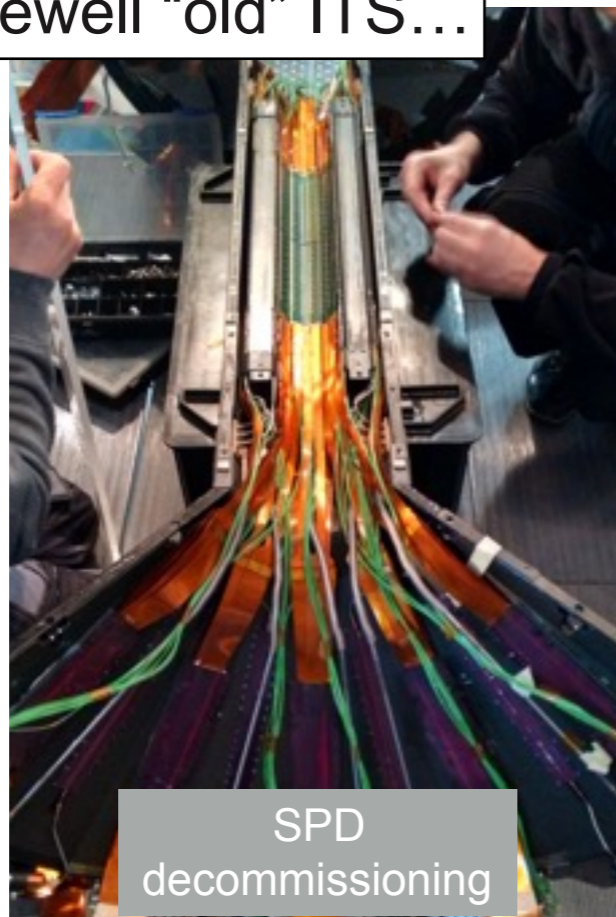
ITS upgrade - Conclusion and outlook



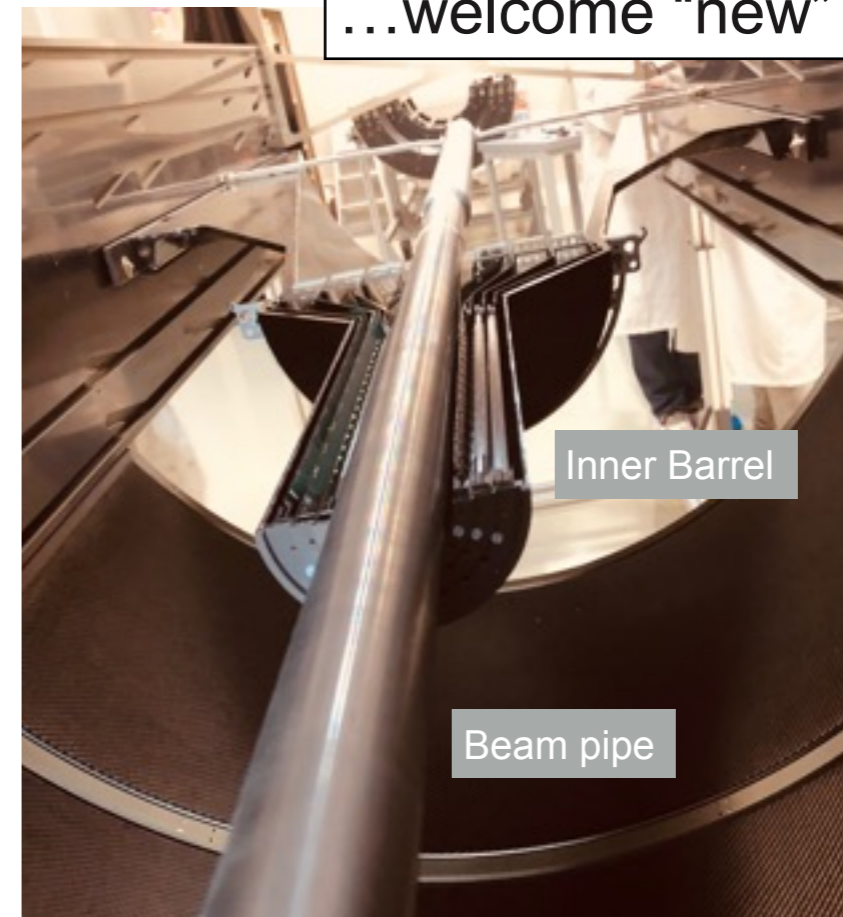
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- » Detector component production completed
- » Stave integration progressing
- » Commissioning on surface started in May 2019 → until May 2020
- » Preparation of P2 services for detector installation on schedule
→ 6 months of commissioning after installation in ALICE

Farewell “old” ITS...



...welcome “new” ITS



Backup



ALICE



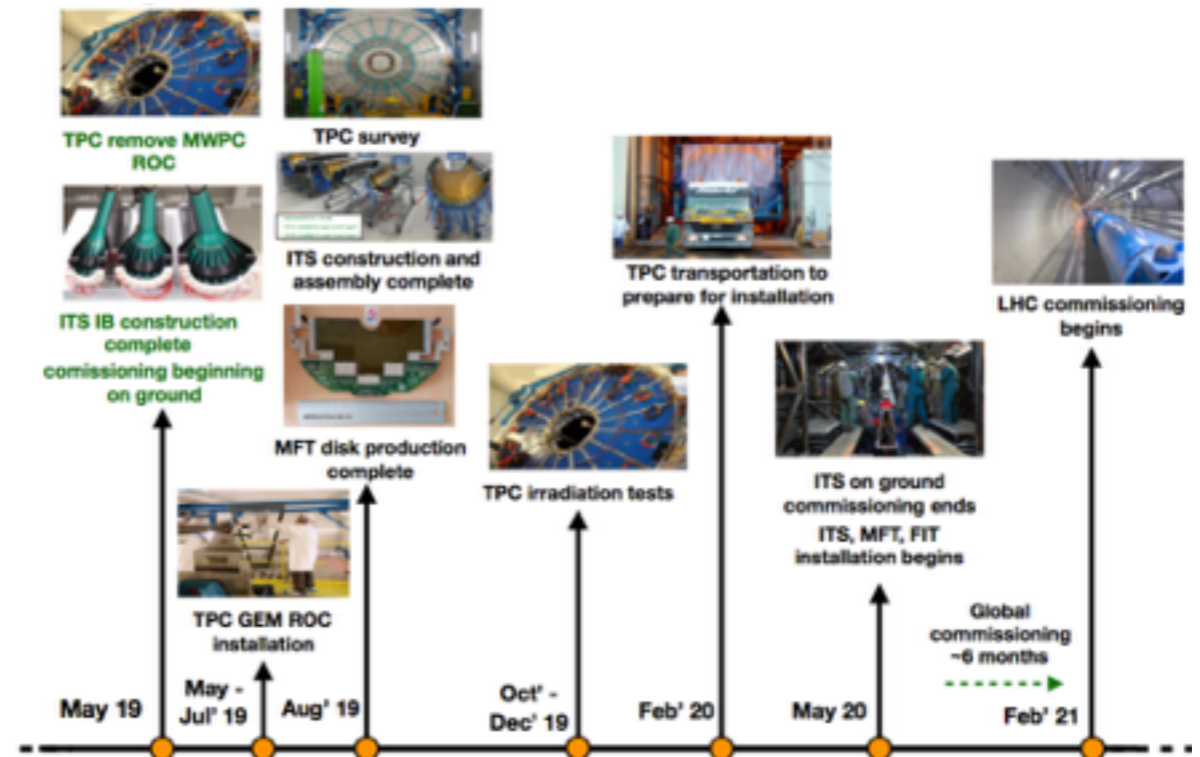
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Backup

LHC Run3/4 program and ALICE Upgrade strategy

4 key objectives identified by HL/HE-LHC working group 5 for high-density QCD at LHC after LS2

1. Characterising the microscopic long-wavelength QGP properties with unprecedented precision
2. Accessing the microscopic parton dynamics underlying QGP properties
3. Developing a unified picture of partial production from small (pp) to larger (p-A and A-A) systems
4. Probing parton densities in nuclei in a broad (x, Q²) kinematic range and searching for possible onset of parton saturation

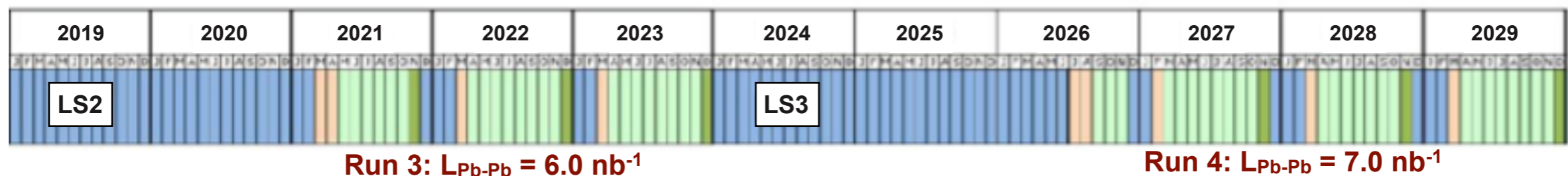


Proposed run schedule for Run 3/4

System	$\sqrt{s}, \sqrt{s_{NN}}$	L_{int}	Note
Pb-Pb	5.5 TeV	13 nb ⁻¹	3 nb ⁻¹ low B-field
p-Pb	8.8 TeV	1.2 pb ⁻¹	
pp	14 TeV	200 pb ⁻¹	High-multiplicity triggered
	8.8 TeV	3 pb ⁻¹	
	5.5 TeV	6 pb ⁻¹	
O-O	7 TeV	500 μb ⁻¹	pilot run
p-O	9.9 TeV	200 μb ⁻¹	

ALICE Upgrade strategy

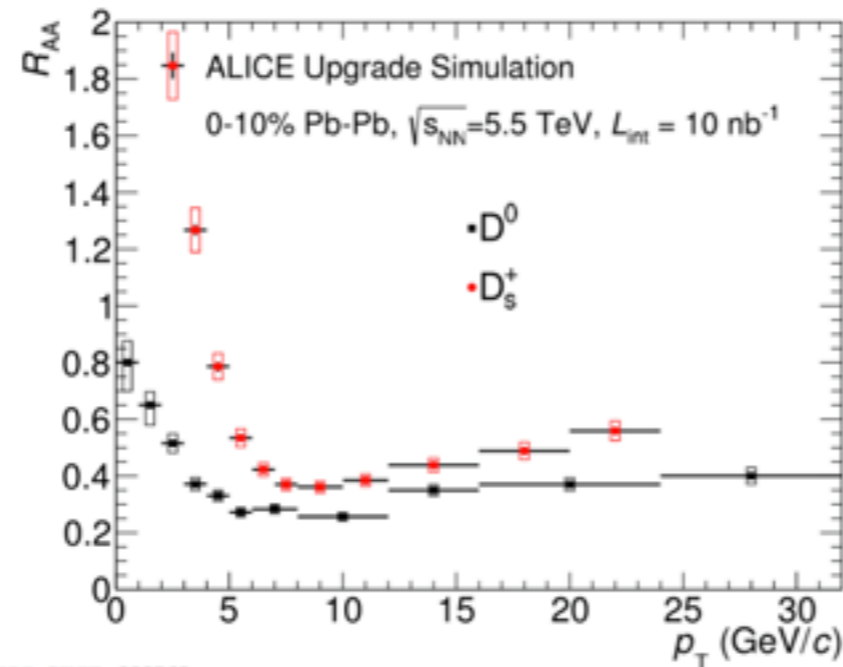
- » New silicon trackers: ITS (mid-rapidity), MFT (forward rapidity)
- » New TPC read-out chambers (GEMs) and electronics
- » New Fast Interaction Trigger (FIT)
- » New Read-out of other detectors (TOF, TRD, Muon arm, ZDC,...)
- » Upgrade of Online and Offline systems (O² project)



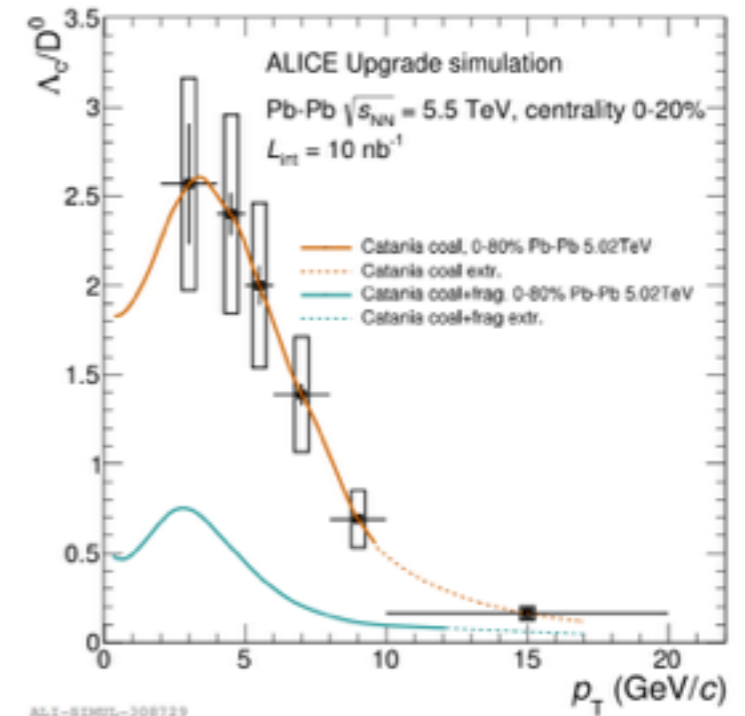


ITS upgrade - Physics performance

» Improvement in the signal extraction for heavy flavour particles, like D^0 and D^+_s

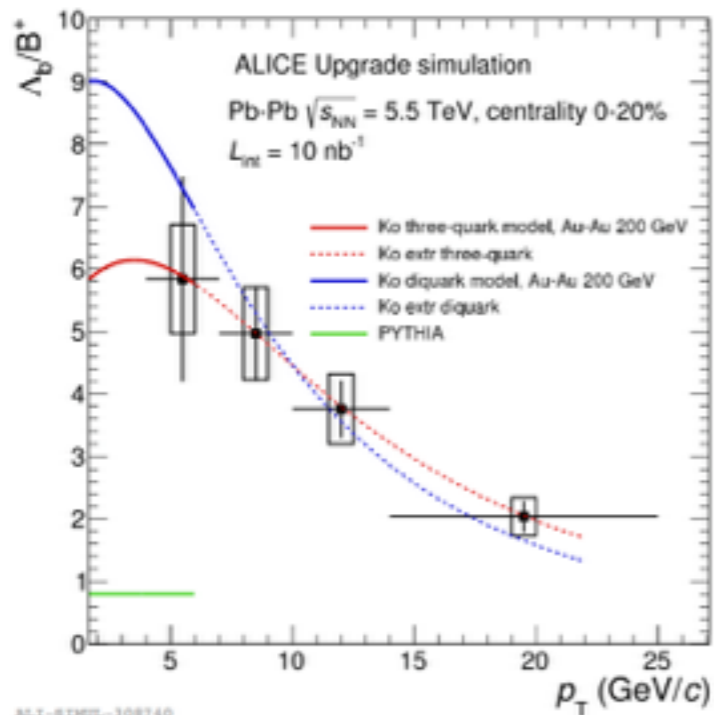


ALI-SIMUL-308768

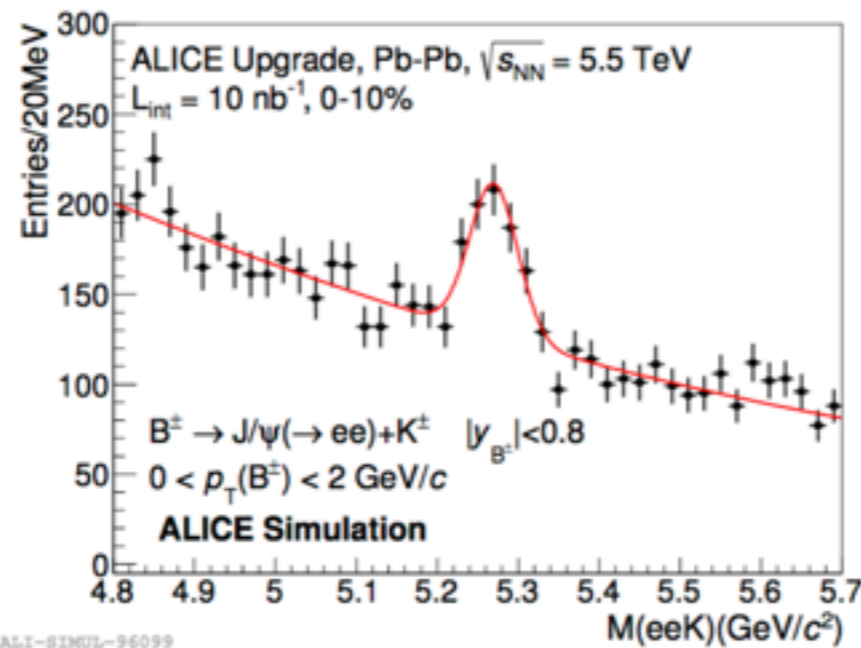


ALI-SIMUL-308729

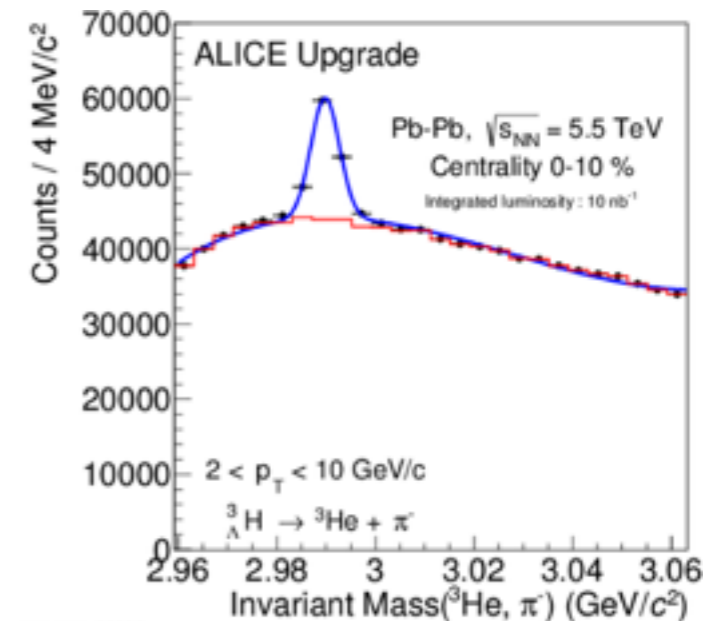
» Allowing measurement of particles not accessible during Run1/Run2, like $^3_\Lambda\text{H}$, B or Λ_b



ALI-SIMUL-308740



ALI-SIMUL-96099



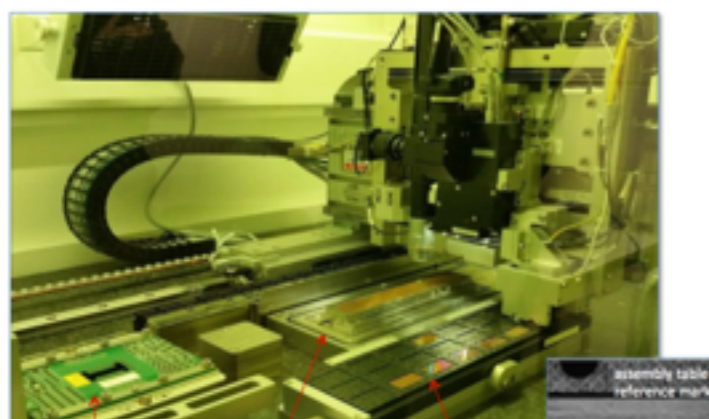
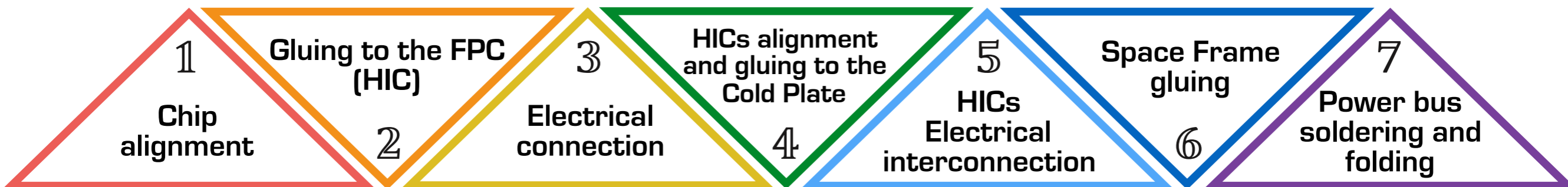
ALI-PUB-80396



ALICE

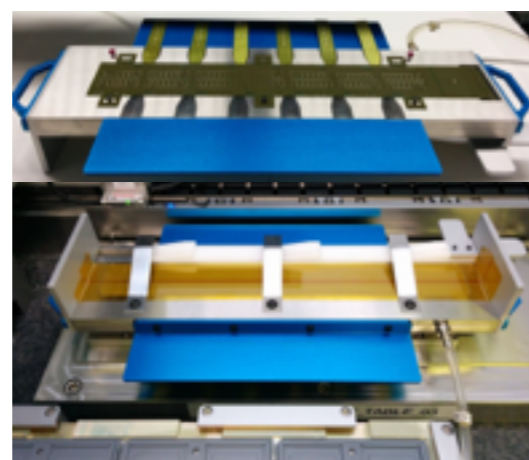
ITS upgrade - Stave assembly workflow

- » Similar assembly procedure for stave in IL, ML and OL
- » Extensive characterisation and quality checks in many assembly steps

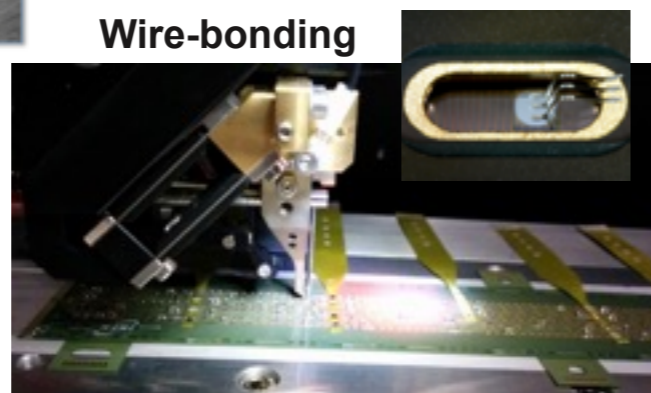


Probe Card Assembly Table Chip Tray

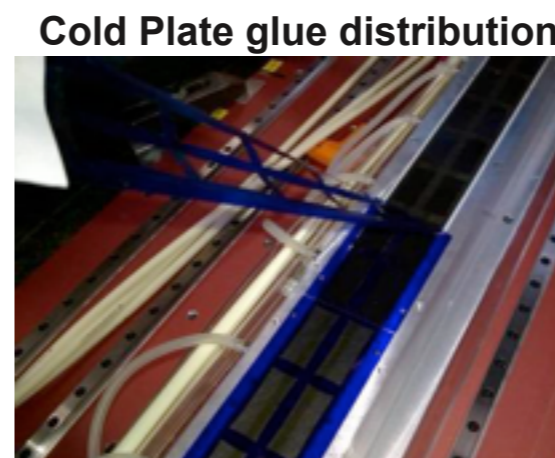
- Module Assembly Machine**
- » 5 μ m precision chip placement
 - » Automatic chip inspection
 - » Chip electrical test



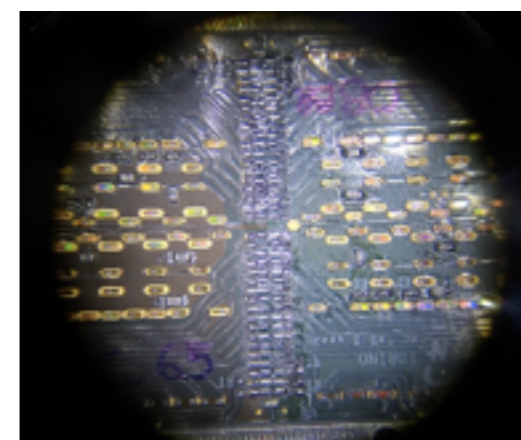
FPC gluing to chips



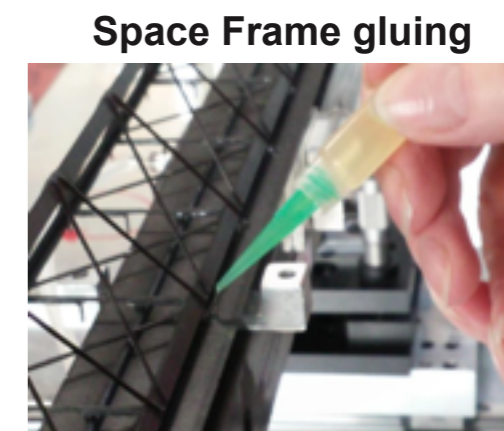
Wire-bonding



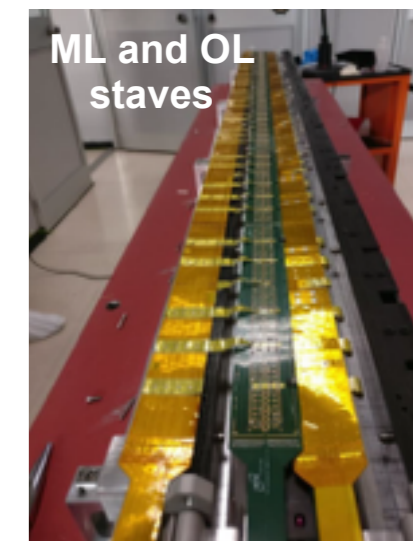
Cold Plate glue distribution



HICs electrical interconnection



Space Frame gluing



ML and OL staves

Power bus folding

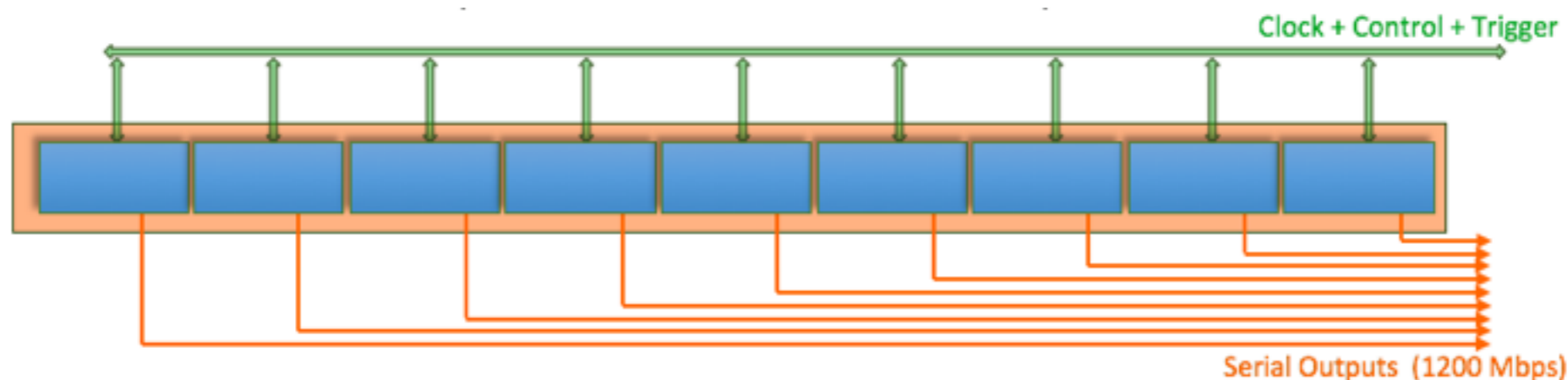


ALICE

Backup

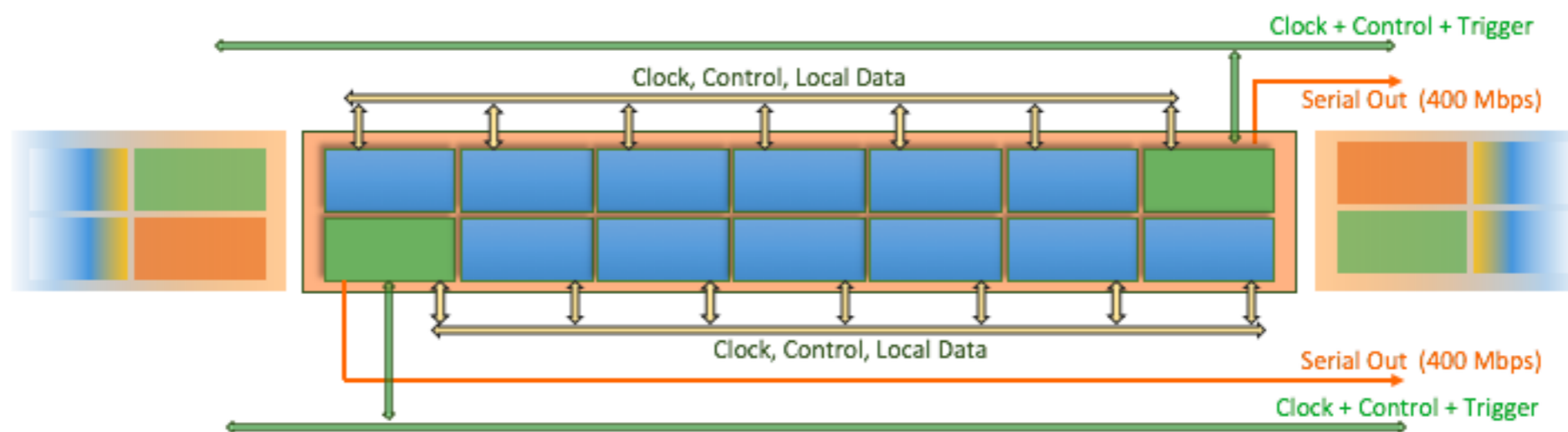
Modules (HICs) readout

ITS Inner Barrel Module – 9 chips, common clock and control, independent data lines



ITS Outer Barrel Module – 2 groups of chips, Master + 6 Slaves

Only the Master interfaces to the external world and bridges control and data transfer





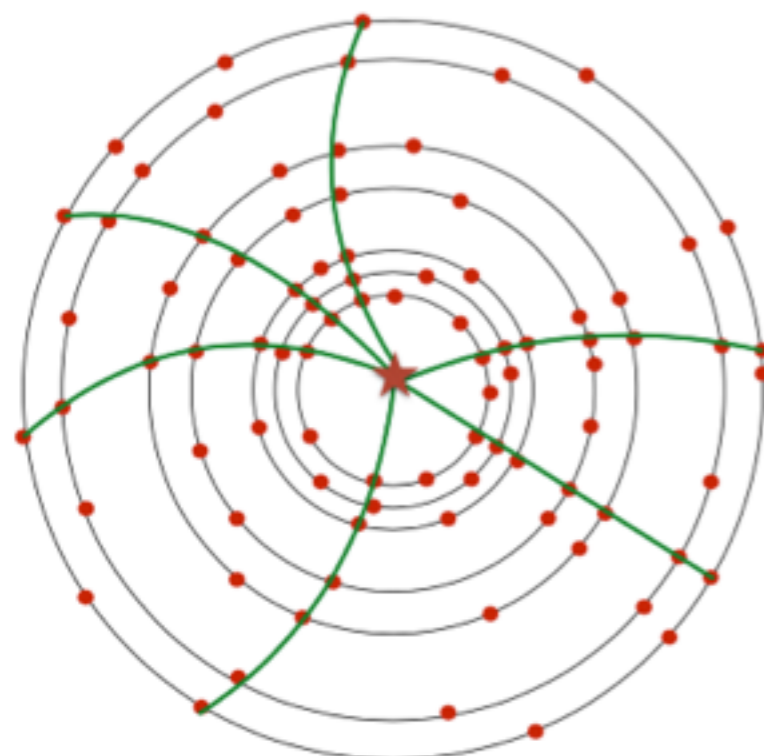
ALICE

Backup

Online tracking and vertexing

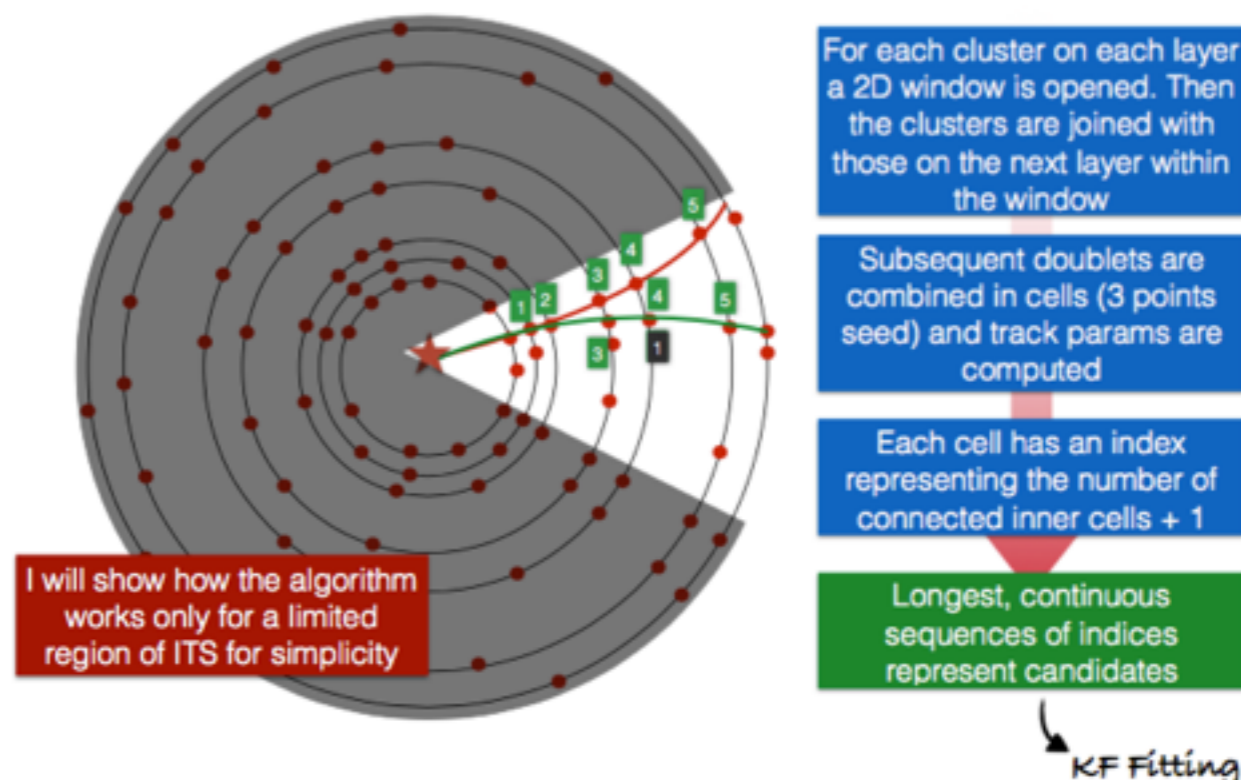
- » Starting from Run3 we expect Pb-Pb collisions at peak rate of 50 kHz
 - 1.1 TB/s of data will be collected
- » Data volume must be reduced before writing to tape
 - Online processing is the only option
- » ALICE is running GPU based online track reconstruction in the TPC since 2010 with good performance
- » From Run 3 on also the reconstruction of tracks and vertices in the ITS will be done on GPU

Tracking in ITS Upgrade



- Determination of the primary vertex with fast algorithms
- Using a pattern recognition method, find track candidates
- Fitting of the candidates using Kalman Filter in three passes (inward, outward, inward)
- Candidates with the best χ^2 are saved as tracks

Cellular Automata in the ITS Upgrade





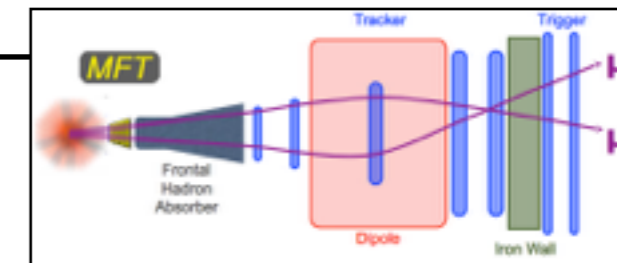
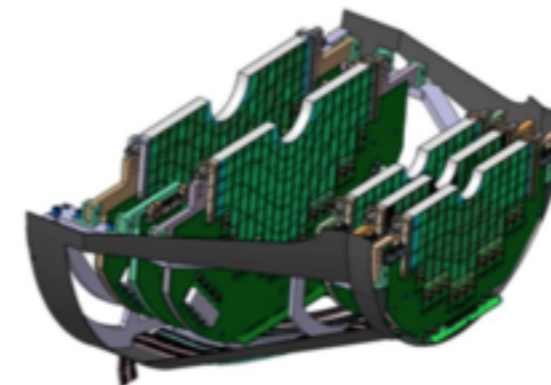
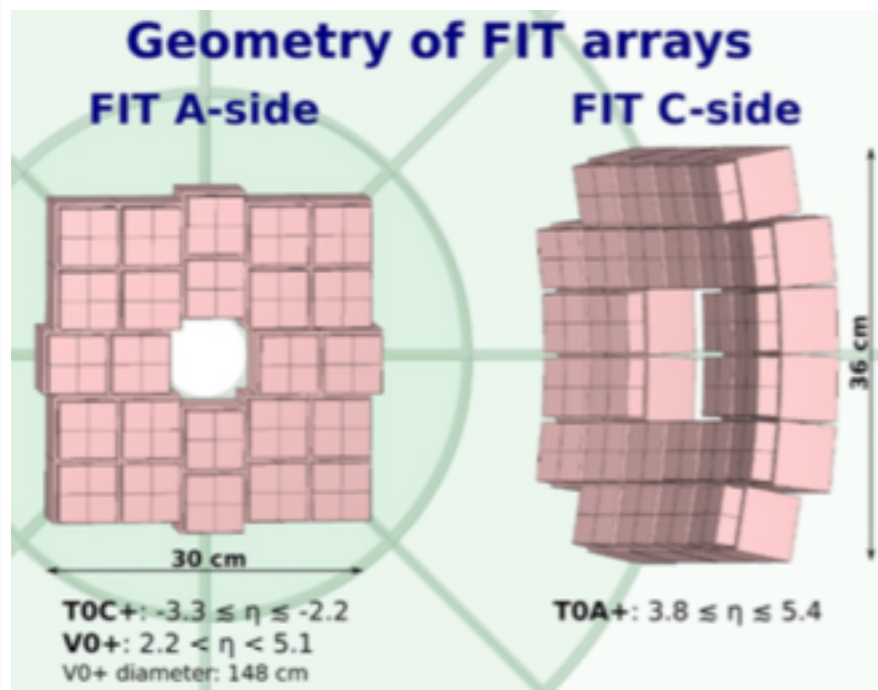
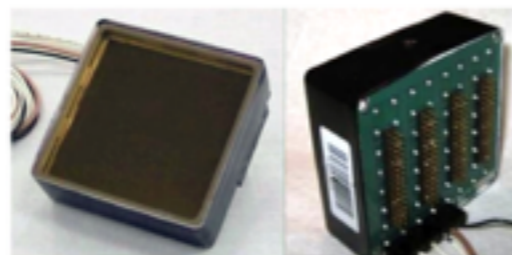
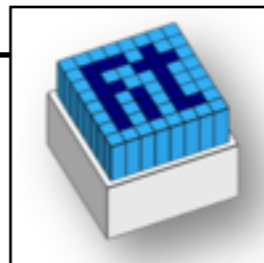
ALICE

Backup - ALICE upgrade

Muon Forward Tracker (MFT) and Fast Interaction Trigger (FIT)

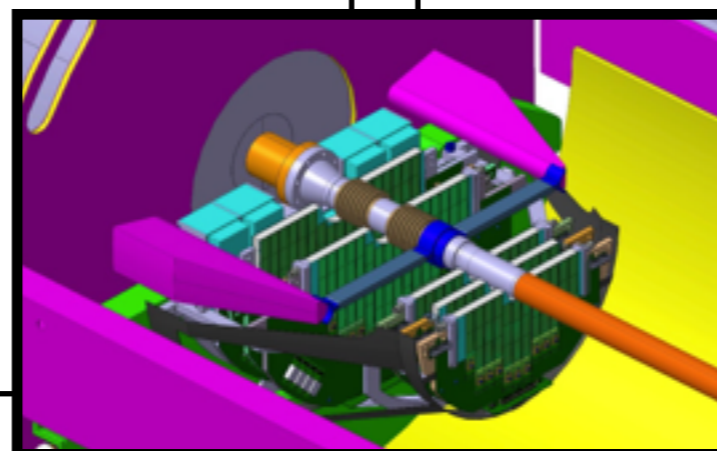
» Minimum Bias Trigger

- Efficiency 100% (~83%) in Pb–Pb (pp) collisions
- Centrality triggering
- Vertex online location
- Time resolution < 50 ps
- Event plane determination
- No ageing over Run3 and Run4 periods



- » Muon tracks are matched between the Muon Spectrometer and MFT
- » MFT adds high pointing accuracy for muon tracks
 - Measurement of displaced vertex position
 - Strong Lorentz boost effect at forward rapidity, event for $p_T = 0$
 - Measurement of beauty down to $p_T = 0$ from displaced J/ψ vertices

- Measurement of $\Psi(2S)$
 - » 10 Half-disks, distributed in 2 detector planes, equipped with 920 ALPIDE chips



Backup - ALICE upgrade

Time Projection Chamber read-out chamber upgrade



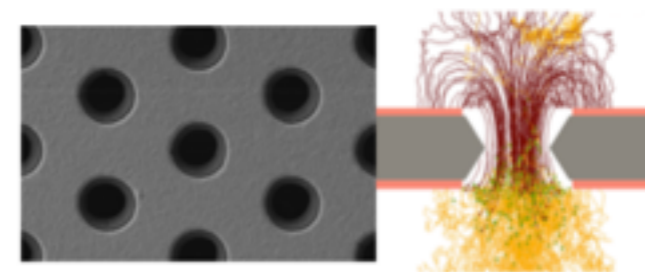
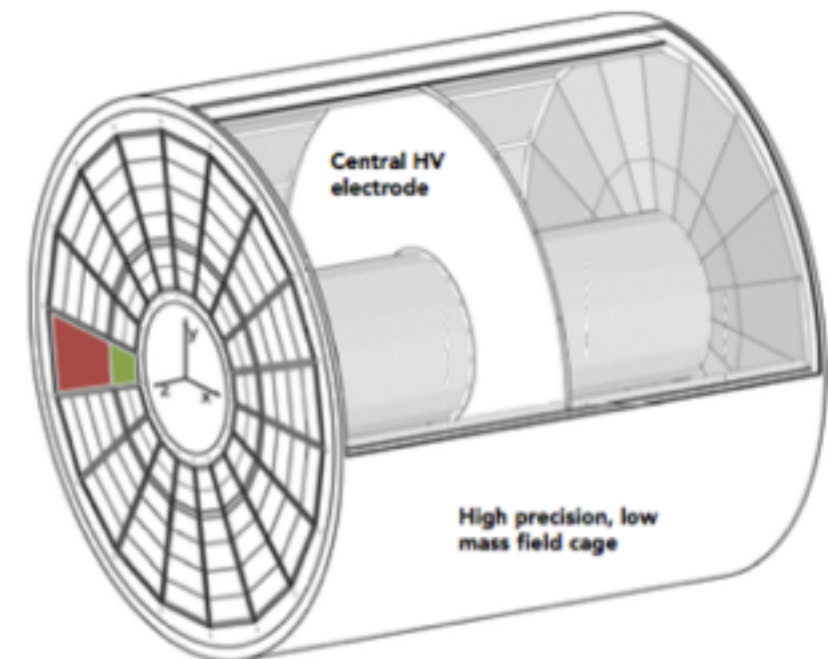
ALICE

Limitation of the ion backflow

- » Diameter: 5 m, Length: 5 m, Electron drift time: $100 \mu\text{s}$, Ion drift time: 160 ms
- » Gating grid to collect ion back flow need $300 \mu\text{s}$ → Intrinsic limitation at 3 kHz interaction rate
- » Present RO limits to 300 Hz for central Pb-Pb collisions
- » Low Ion back flow of Gas Electron Multipliers (GEMs) allows to avoid gating grid
- » New RO architecture: continuous readout → $\sim 3 \text{ TByte/s}$
- » Online calibration, reconstruction and data compression needed (O² project)

GEM technology

- » Quadrupole GEM chambers
- » GEMs technology intrinsically blocks ion backflow
- » Similar performances as MWPC
- » 640 GEM foils needed for the TPC RO upgrade



Backup - ALICE upgrade

O² project



ALICE

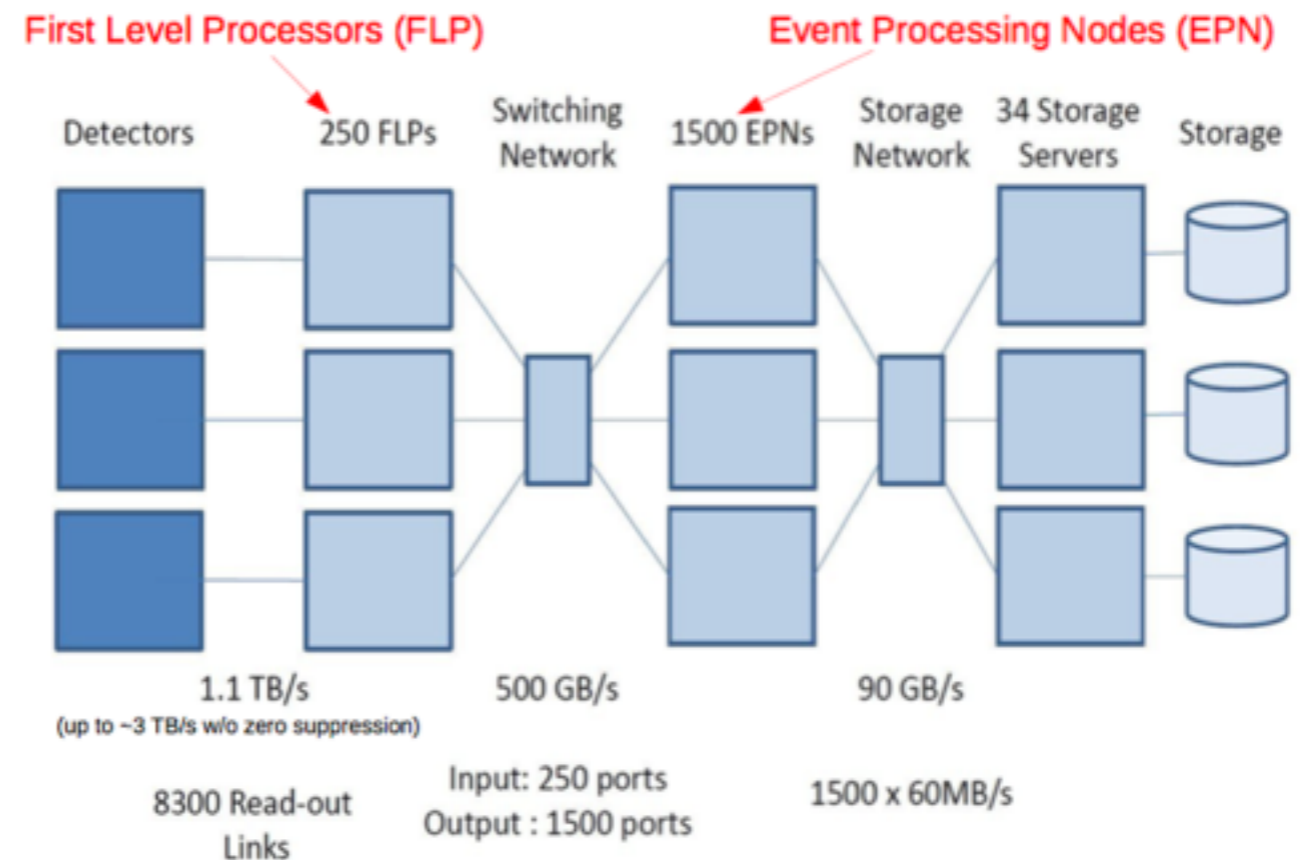


Requirements

1. LHC min. bias Pb-Pb at 50 kHz, ~100 x more data than Run1/2
2. Rare physics processes with very small signal over background ratio
3. Triggering techniques very inefficient if not impossible
4. TPC inherent rate > 50 kHz → Support for continuous read-out

New computing system

- ➔ Read-out the data of all interactions
- ➔ Compress these data intelligently by online reconstruction
- ➔ One common online-offline computing system: O²



- First Level Processors (FLP) receive continuous data from parts of detectors and perform local tasks like cluster-finding, mask creations etc.
- Each FLP chops the output data to SubTimeFrames (~20 ms long) and dispatches STF of the same time stamp to one of the Event Processing Nodes (EPN)
- EPN performs full TPC reconstruction to compress the data and **partial (a few % only)** reconstruction of other detectors to produce enough calibration data. Aggregates STF to single TimeFrame (TF).
1500 EPNs → ~30 s of real time to process TF

- ◆ Calibration data of different EPNs aggregated, CCDB populated with calibration objects
- ◆ Final reconstruction in all detectors, matching, vertexing performed for each TF
- ◆ Compact AODs written per TF (up 1000 consecutive events in Pb-Pb @ 50kHz)
- ◆ AOD design will be aimed at storage minimization